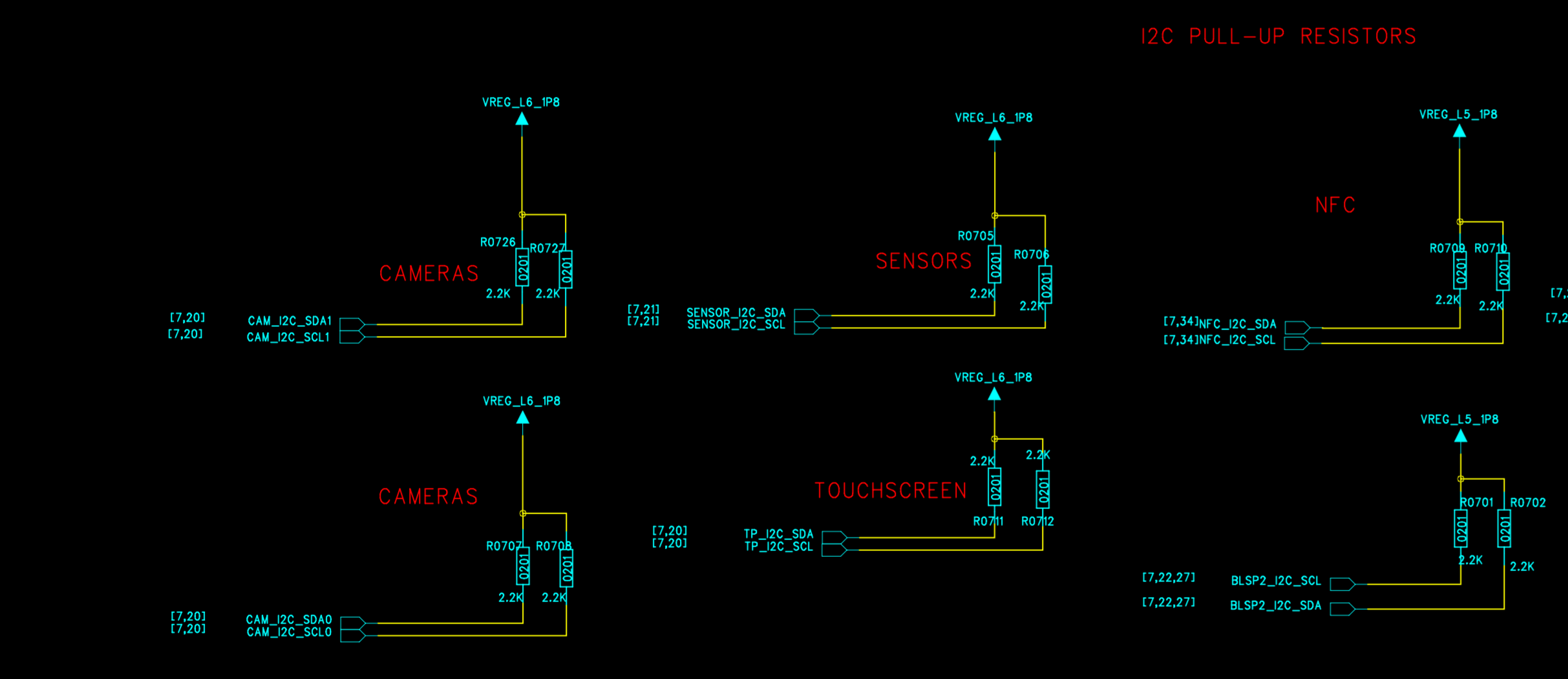
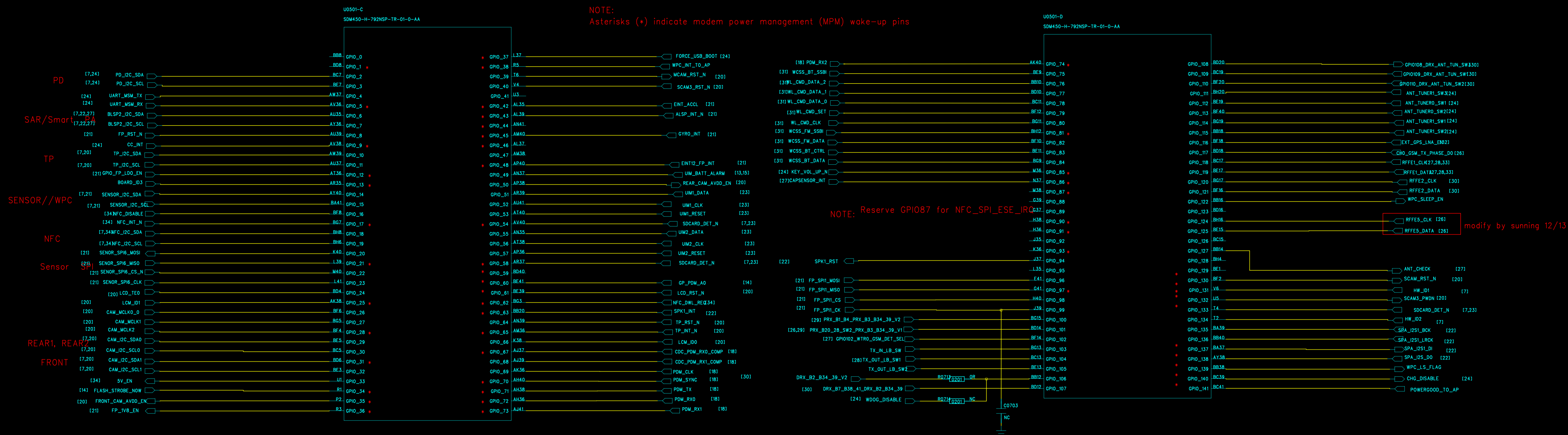


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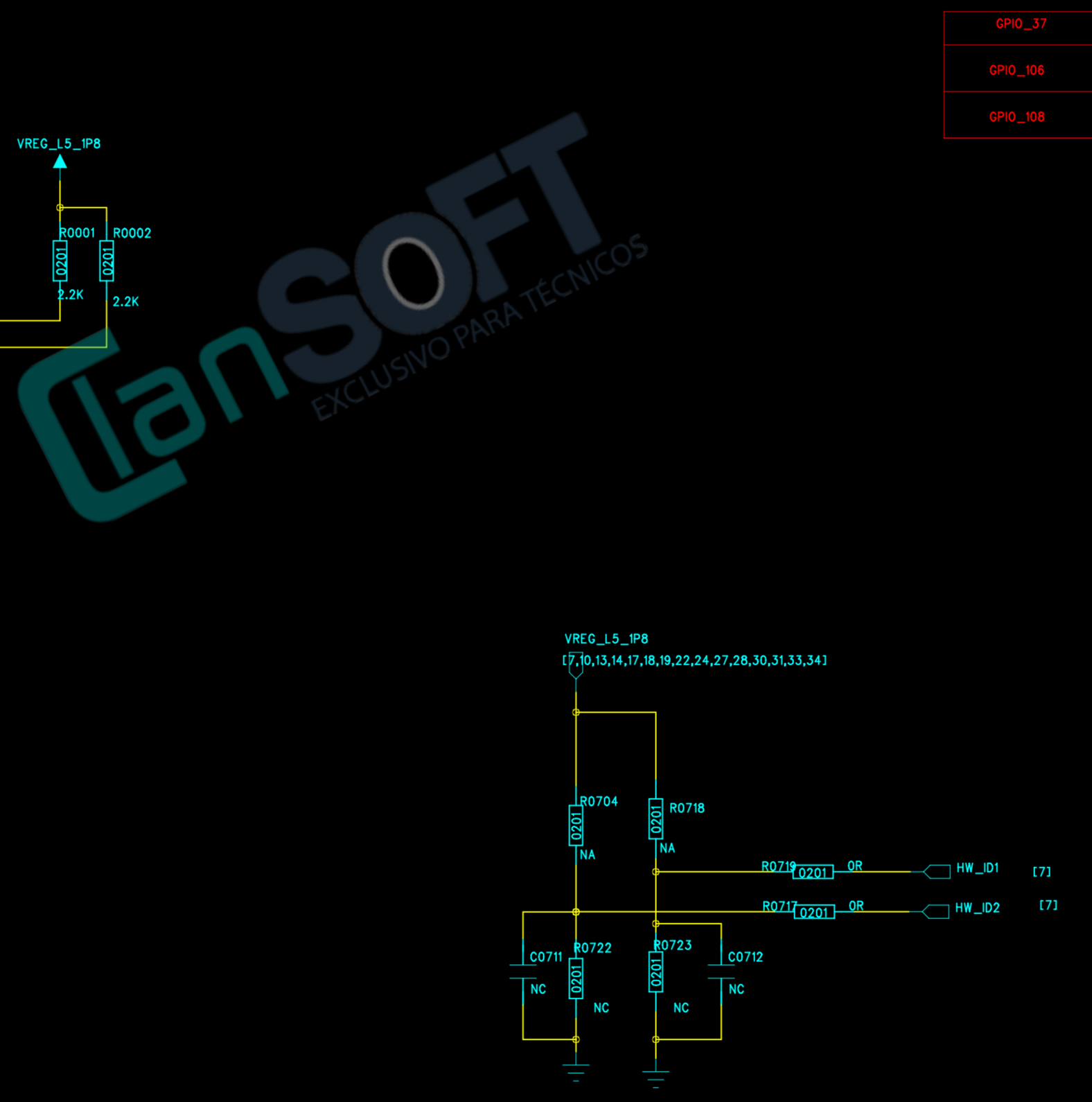
### MSM8953 EBI

QUALCOMM Technology Resources Drive  
12066 Joshua Drive  
San Diego, CA 92130-1714  
U.S.A.

Title	Sheet	Rev
Size	Name	Date
Drawn	Checked	By



NOTE:  
Ensure SW sets these GPIOs (Sensor, CTP and Camera I2C bus) to input pull-down when the peripherals are powered off to eliminate leakage.



GPIO_37	FORCED_USB_BOOT
GPIO_38	WDOG_DISABLE
GPIO_39	APPS_BOOT_FROWN_PIN

BOOT_CONFIG(31)	BOOT_CONFIG
0x000	SOC1 -> SOC2 -> USB2.0
0x001	SOC2 -> SOC1 -> USB2.0
0x002	SOC1 -> USB2.0
0x003	USB2.0

Default Boot Config (0x000) is SOC1(SOC)

### MSM8953 GPIO

















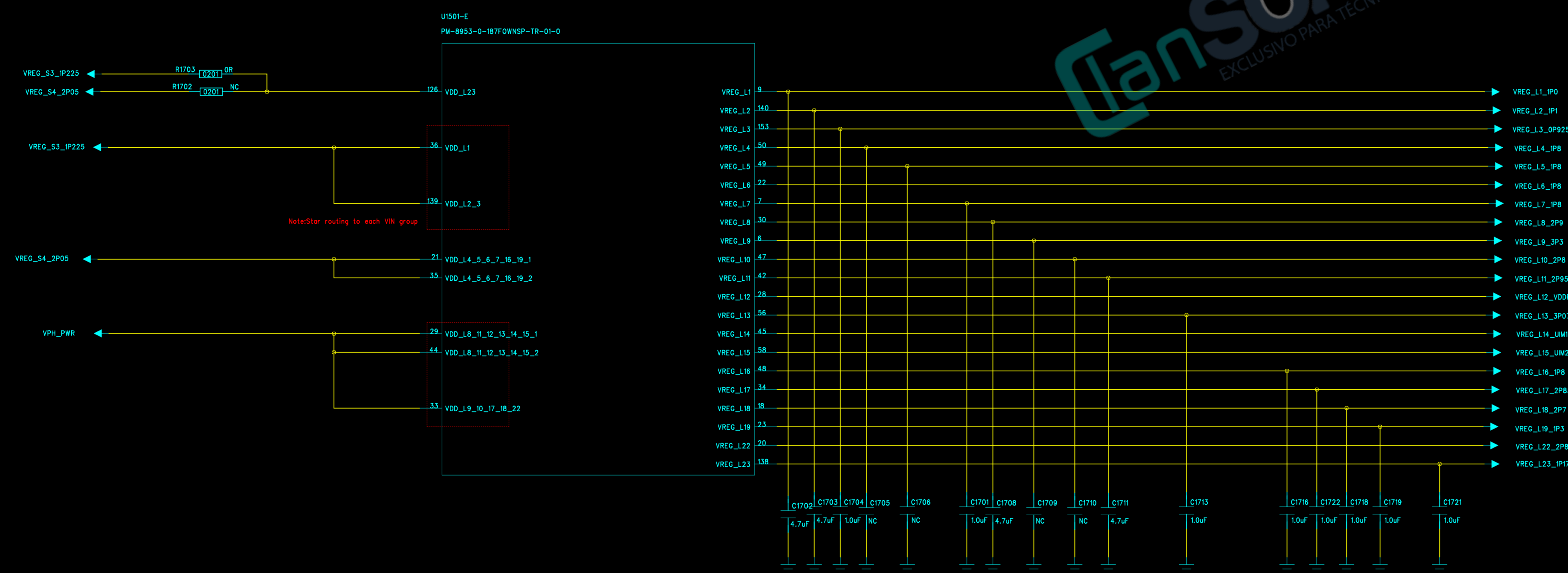












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**Table 3-6 PM8937/PM8940 regulators and their intended uses**

Function	Circuit type	Default V (V) <sup>1</sup>	Specified range (V) <sup>2</sup> (MSM8937)	Programmable range (V)	Rated current (mA)	Default on	Expected use (MSM8937)	
S1	ULT-SMPS	1.225	0.900–1.350	0.375–1.5625	2000 <sup>3</sup>	N	MSM modem	
S2	ULT-SMPS	1.225	0.550–1.350	0.375–1.5625	3000	Y	MSM core and graphics	
S3	HF-SMPS	1.288	1.200–1.4125	0.375–1.5625	2700	Y	Low-voltage LDOs (1, 2, 3, 19, and 23)	
S4	ULT-SMPS	2.050	1.800–2.050	1.550–3.126	2500	Y	High-voltage LDOs (4, 5, 6, 7, 16, RFCLK, and XO)	
S5	FT-SMPS	1.225	1.050–1.350	0.350–1.355	3000	Y	MSM applications processor	
S6	FT-SMPS	1.225	1.050–1.350	0.350–1.355	3000	N	MSM applications processor	
L1	NMOS LDO	1.000	1.000	0.375–1.5375	1200	N	RFICs	
L2	NMOS LDO	1.200	1.200	0.375–1.5375	1200	Y	LPDDR2/LPDDR3, MIPI CSI, and DSI	
L3	NMOS LDO	1.225	0.750–1.350	0.375–1.5375	1200	Y	VDDMX	
L4	PMOS LDO	1.800	1.800	1.750–3.3375	450	N	RFICs and GPS eLNA	
L5 <sup>4</sup>	PMOS LDO	1.800	1.800	1.750–3.3375	500	Y	Most digital I/Os, MSM pad groups 3 and 7, LPDDR, and eMMC	
L6	PMOS LDO	1.800	1.800	1.750–3.3375	300	N	MSM DSI PLL and OTP, camera, touchscreen, display, and sensors	
L7	PMOS LDO	1.800	1.800	1.750–3.3375	150	Y	MSM analog and PLLs, WCN XO, and PM baseband clock driver	
L8	PMOS LDO	2.900	2.900	1.750–3.3375	600	Y	eMMC	
L9	PMOS LDO		$V_{out} = 3.3\text{ V}$ for $VBAT > 3.575\text{ V}$ ; $V_{out} = 3\text{ V}$ for $VBAT < 3.575\text{ V}$	3.000–3.300	1.750–3.3375	600	N	WCN
L10	PMOS LDO	2.8	2.800	1.750–3.3375	150	N	Sensors	
L11 <sup>5</sup>	PMOS LDO	2.950	2.950	1.750–3.3375	800	Y	Micro SD	
L12 <sup>4</sup>	PMOS LDO	2.950	1.800/2.950	1.750–3.3375	150	Y	MSM pad group 2 and SDC2	
L13	PMOS LDO	3.075	3.075	1.750–3.3375	50	Y	MSM USB and audio	

L14 <sup>5</sup>	PMOS LDO	1.800	1.800/2.925/3.050	1.750–3.3375	50	N	MSM pad group 5, dual-voltage UIM1, and
L15 <sup>5</sup>	PMOS LDO	1.800	1.800/2.925/3.050	1.750–3.3375	50	N	MSM pad group 6 and dual-voltage UIM
L16	PMOS LDO	1.800	1.800	1.750–3.3375	5	N	PMIC HKADC
L17	PMOS LDO	2.850	2.850	1.750–3.3375	600	N	Camera, display, and touchscreen
L18	PMOS LDO	2.700	2.700	1.750–3.3375	150	N	QTI RF front-end
L19	NMOS LDO	1.350	1.350	0.375–1.5375	1200	N	MSM analog, WCN, and WGR
L20	Low-noise LDO	1.74	1.74	1.74–3.3375	5	Y	PMIC XO circuits
L21	Low-noise LDO	1.74	1.74	1.74–3.3375	5	Y	PMIC RF clock buffers
L22	PMOS LDO	2.800	2.800	1.750–3.3375	300	N	Camera – analog
L23	NMOS LDO	1.3	1.2	0.375–1.5375	300	N	Camera – digital

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PM8953 LDO

QUALCOMM Technologies, Inc.  
5950 La Tijera Blvd.  
San Diego, CA 92121-7174  
U.S.A.

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Date: \_\_\_\_\_

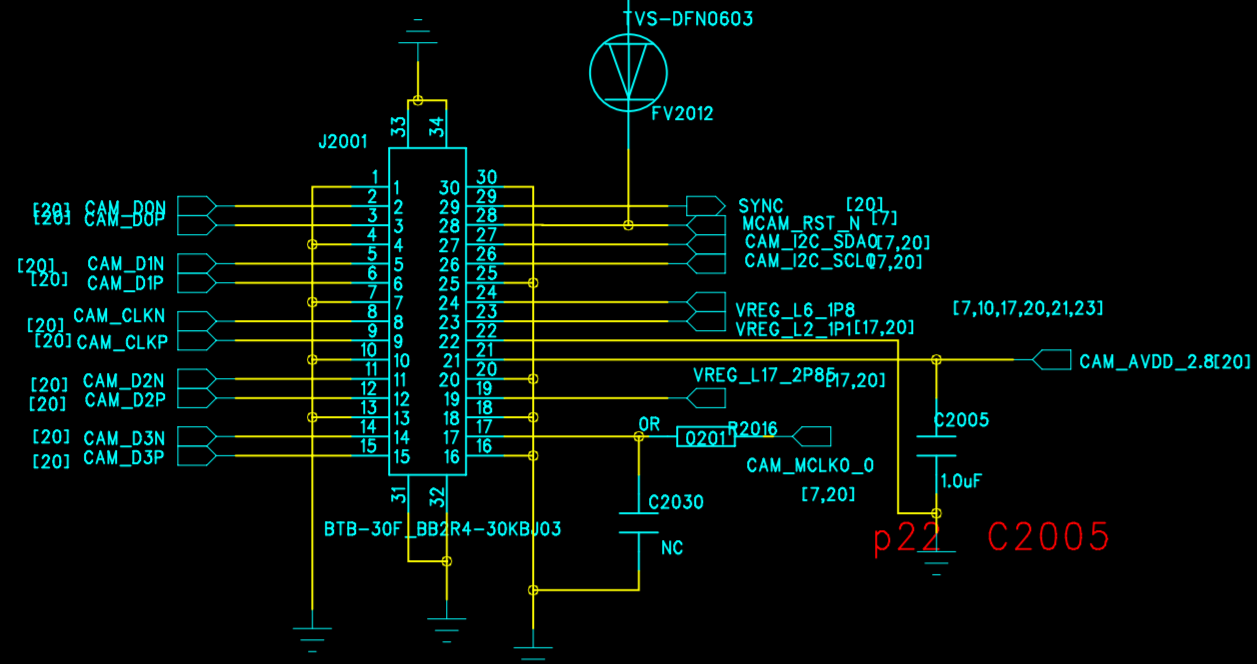
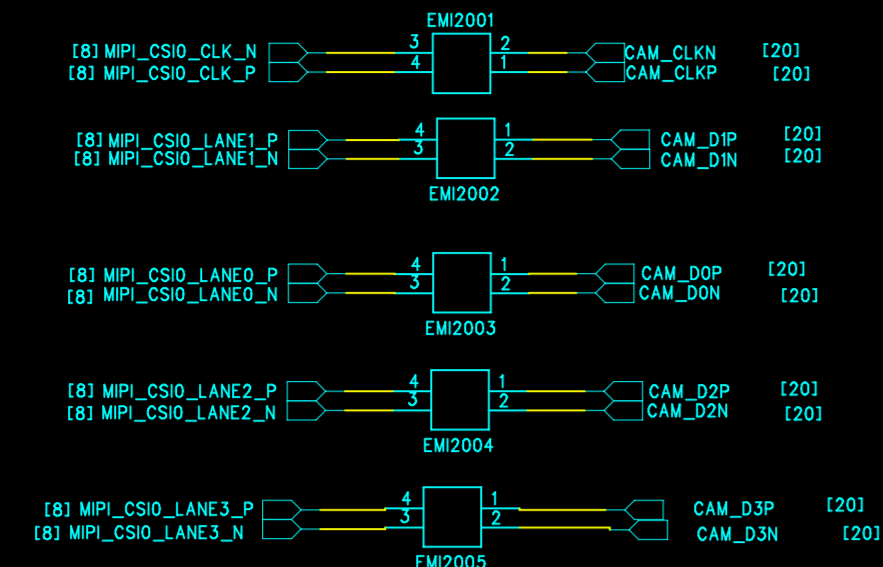






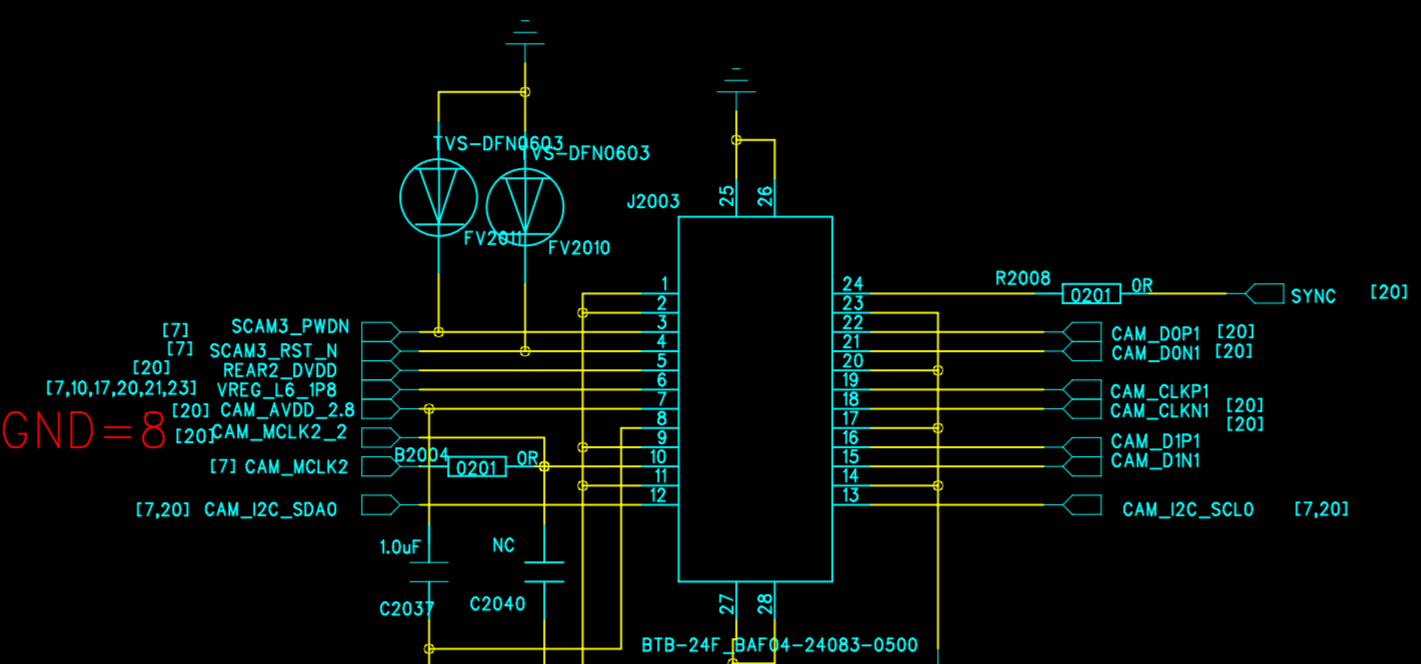
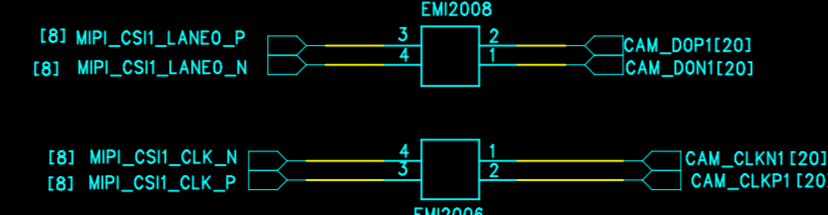
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LTN	ECO NO.	APPROVED	DATE

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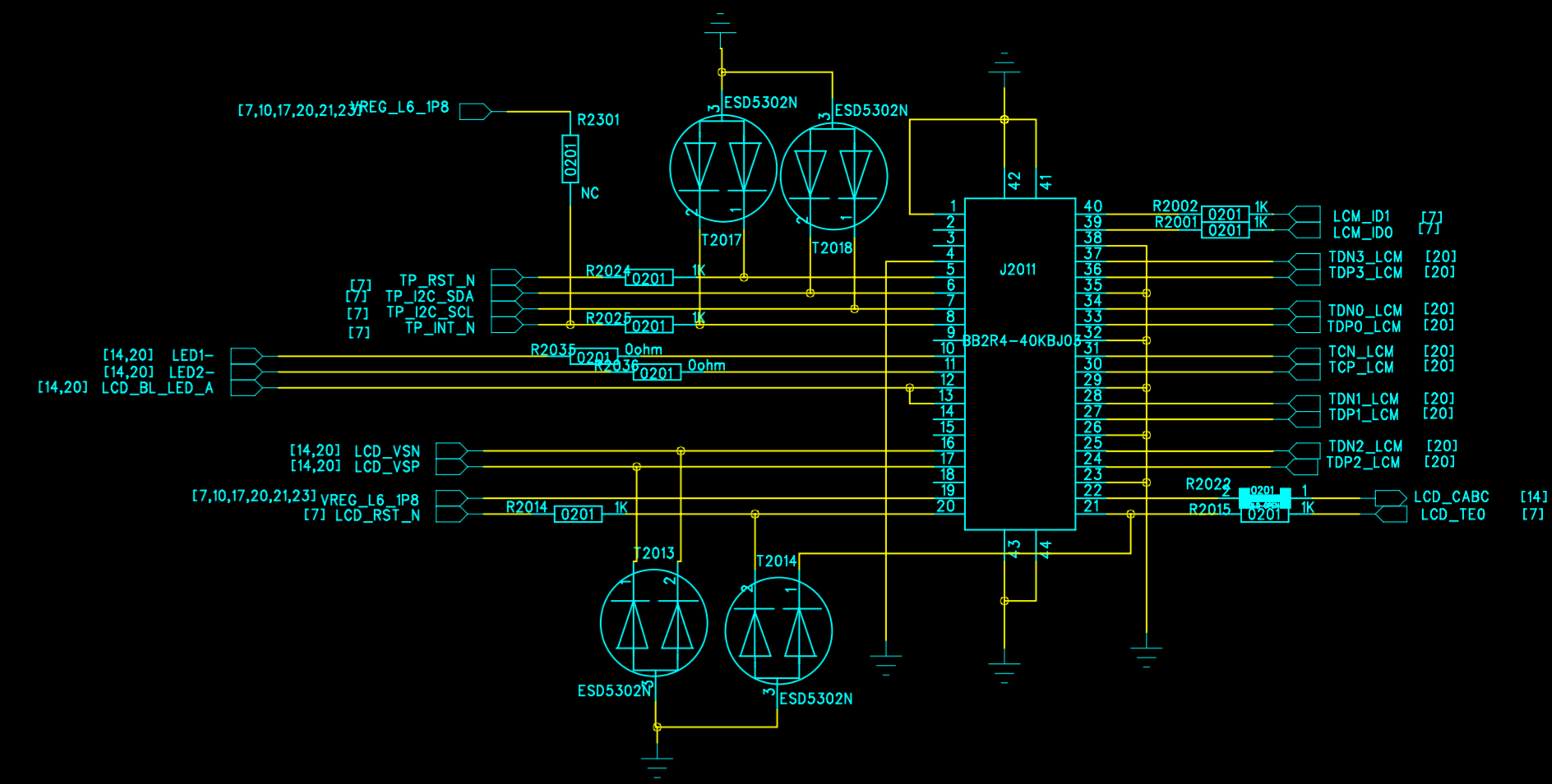


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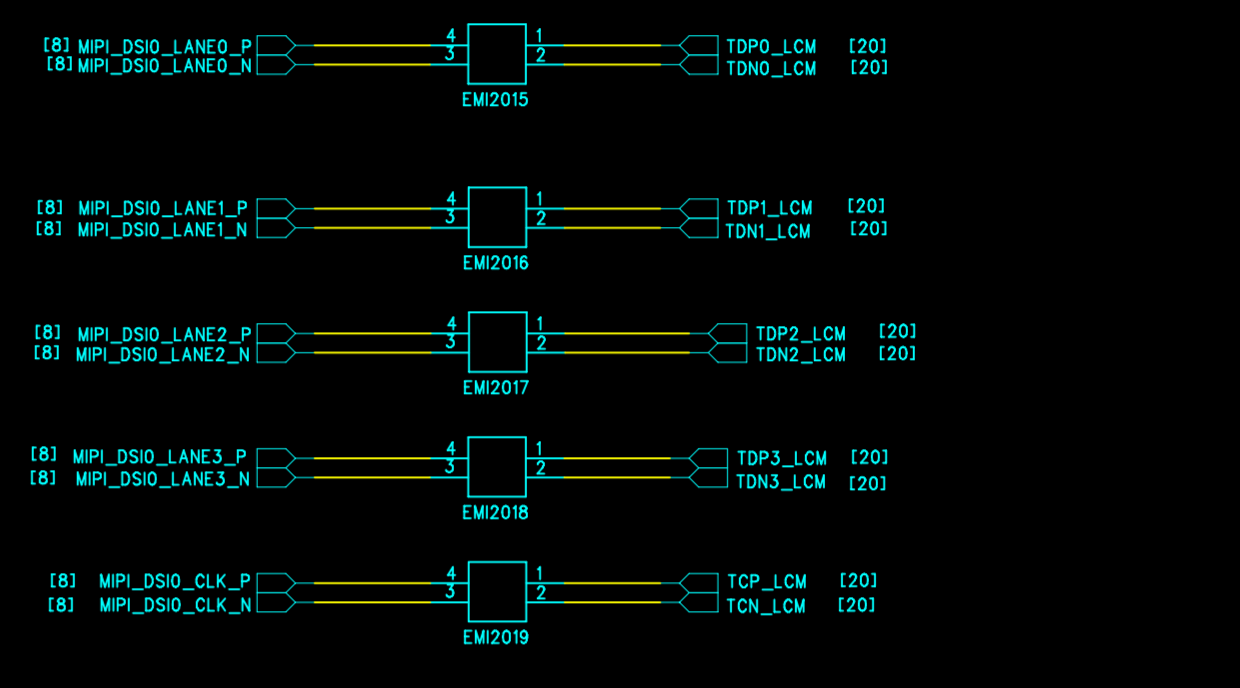
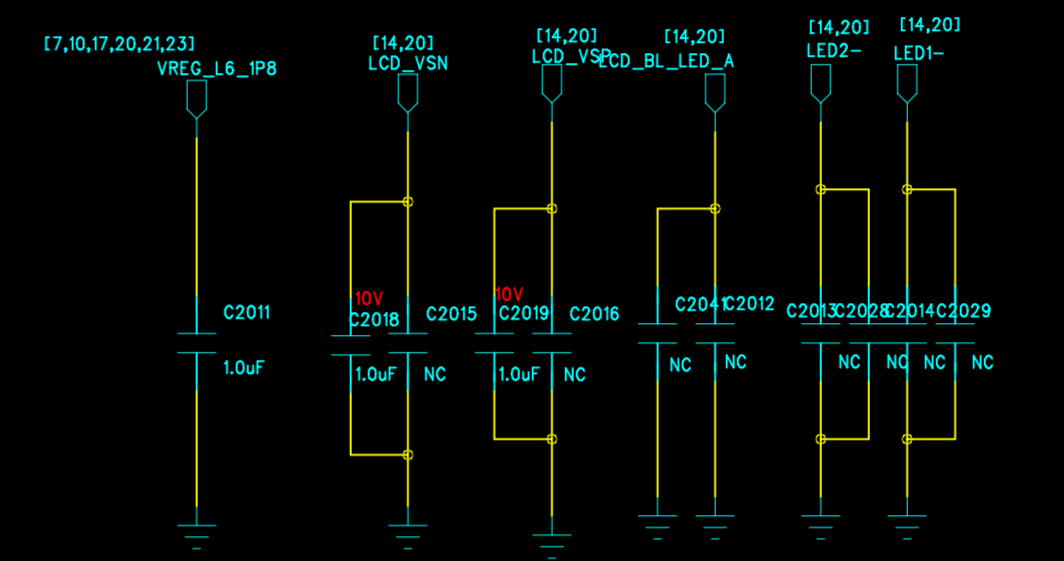
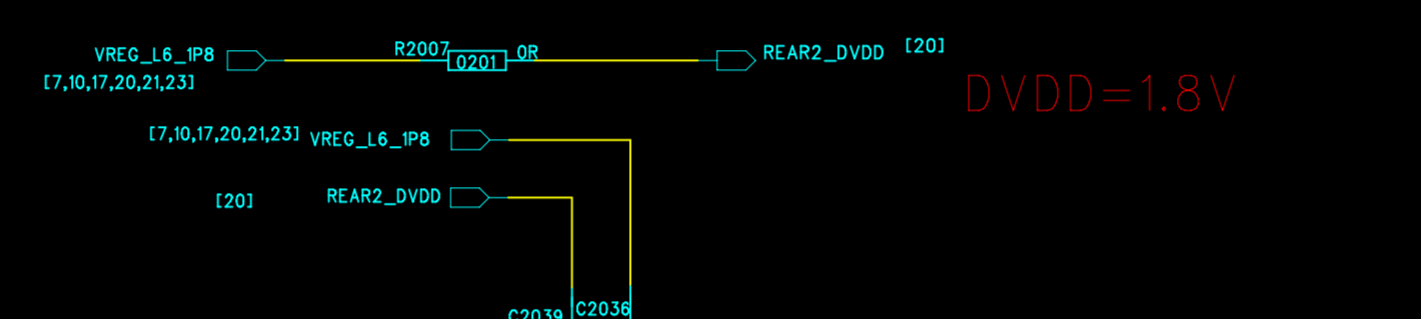
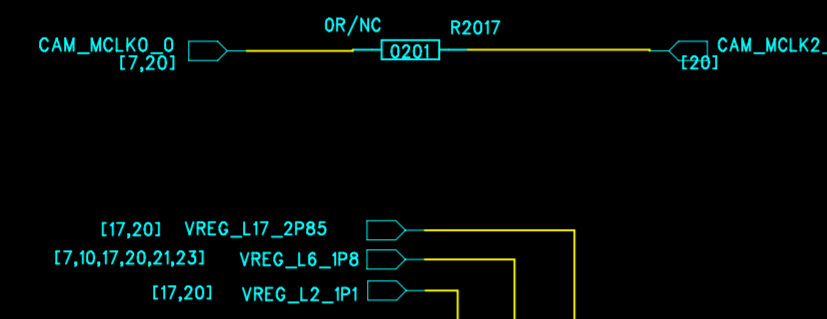
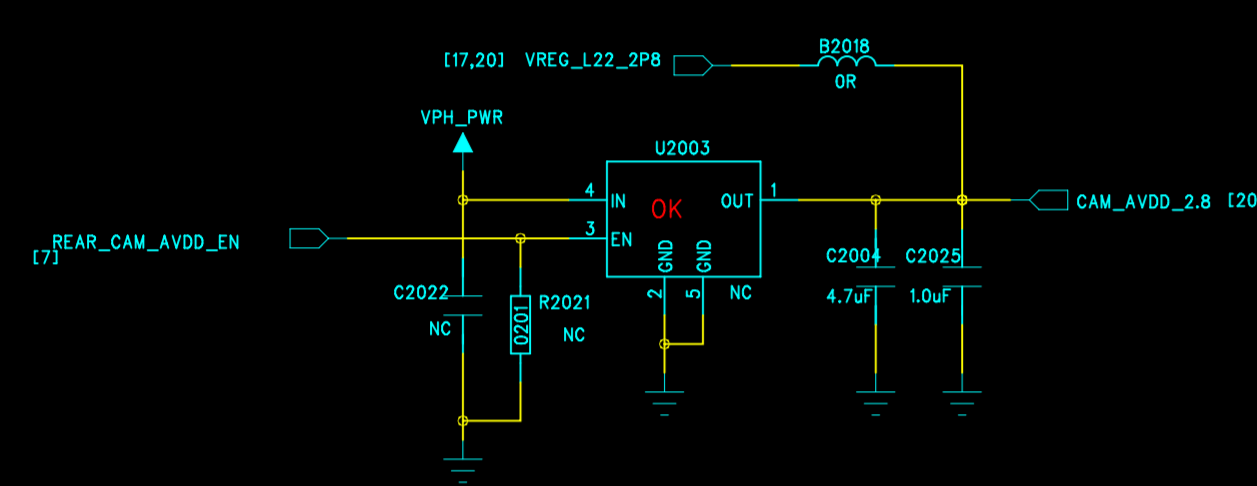
# Main Camera B



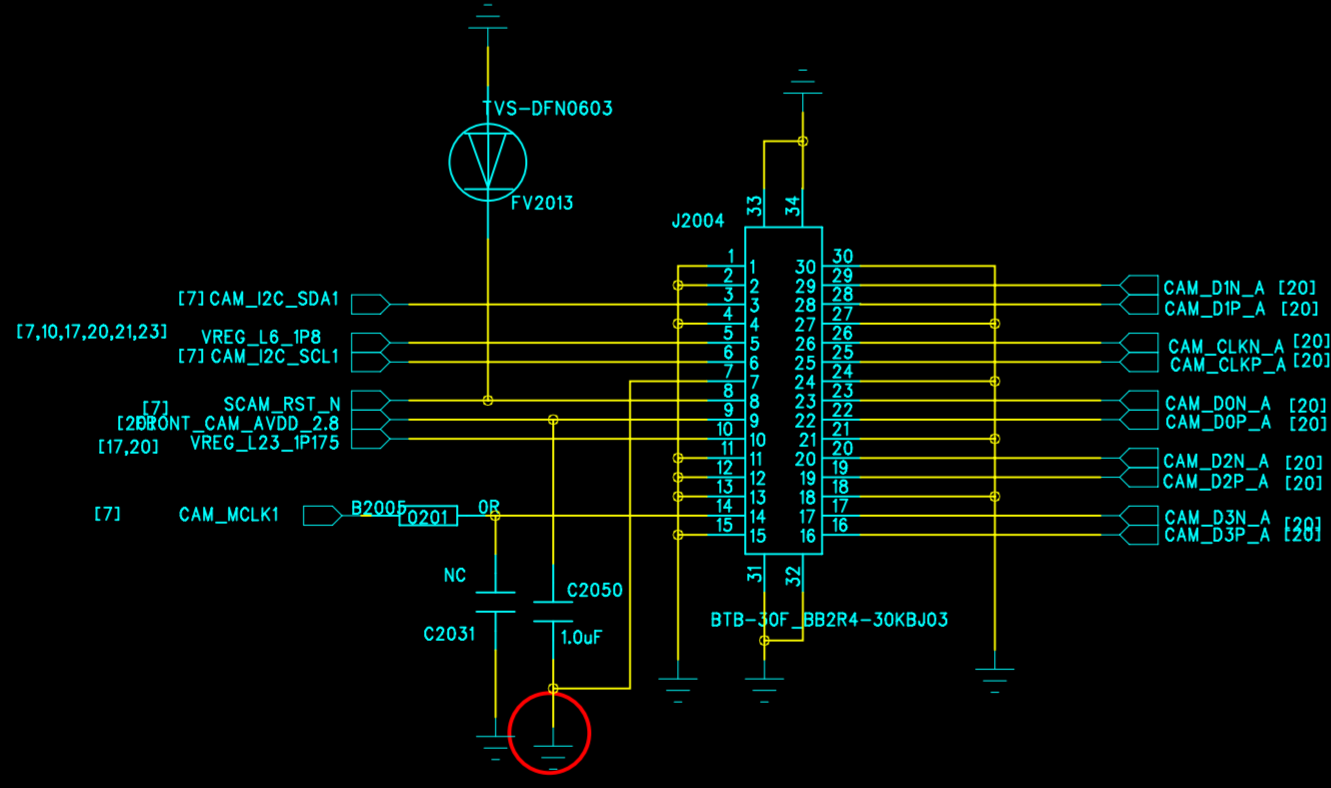
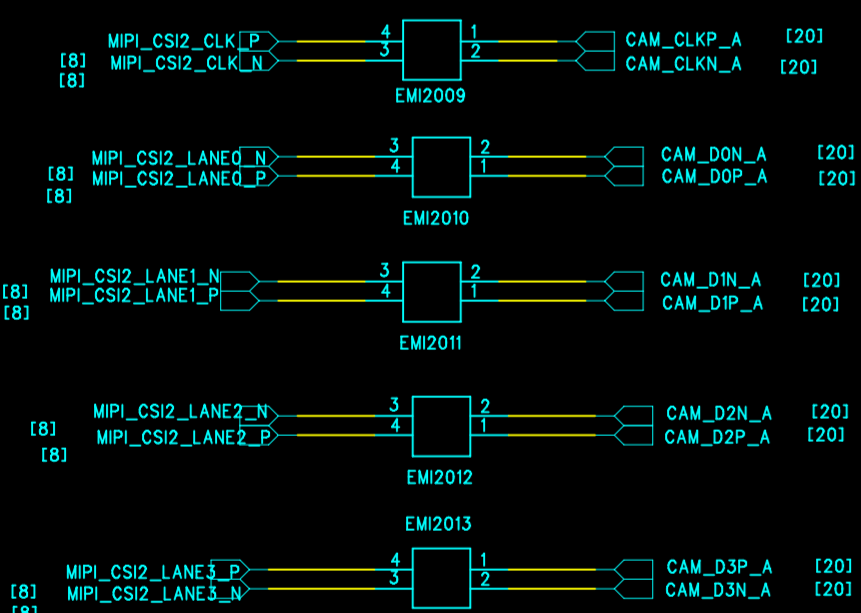
# LCM



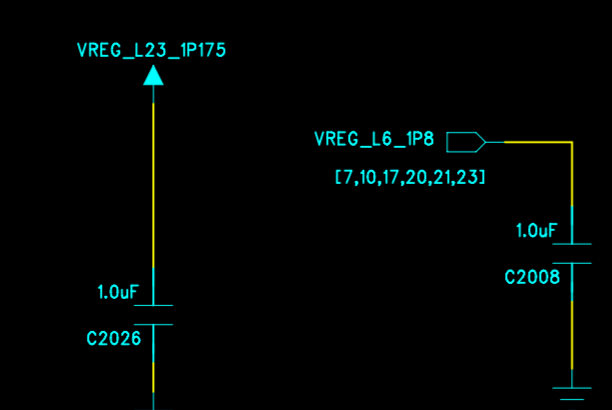
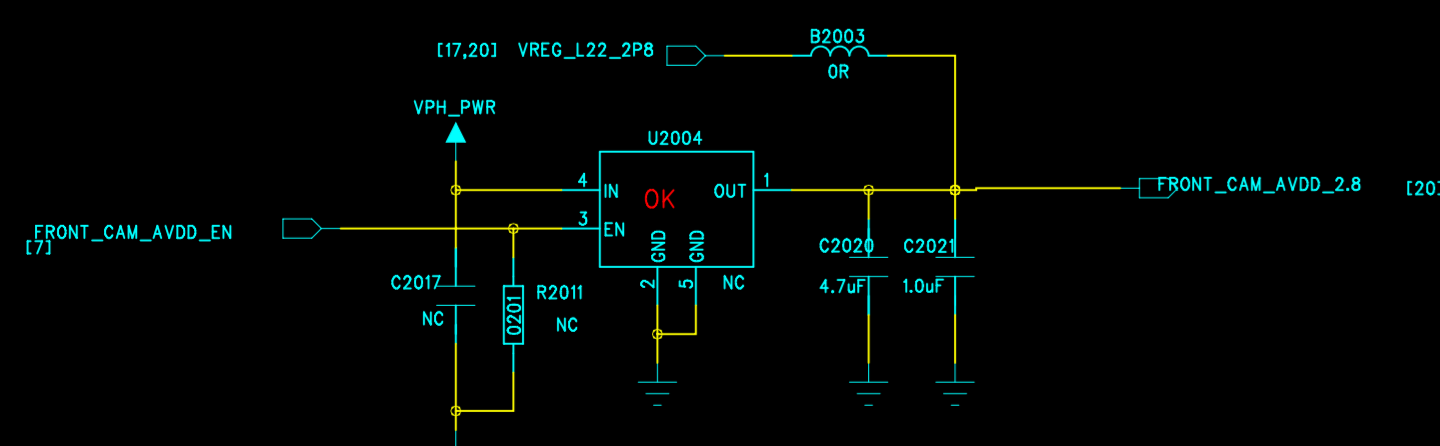
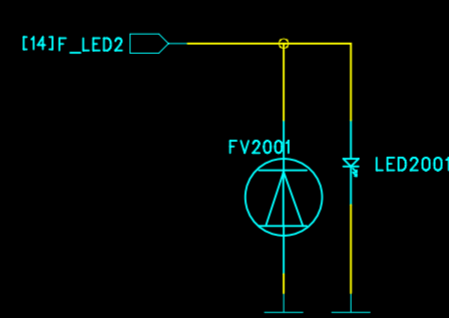
LTN	ECO NO.	APPROVED	DATE



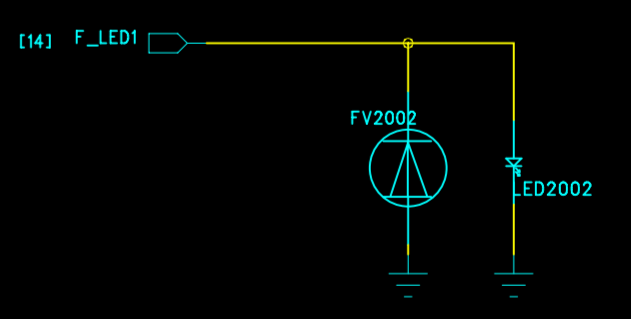
# Front Camera



1	DGND
2	DGND
3	SDA
4	DGND
5	DOVDD
6	SCL
7	AGND
8	RESET
9	AVDD
10	DGND
11	DGND
12	DGND
13	DGND
14	XCCLK
15	DGND
16	MDP3
17	MDN3
18	DGND
19	MDP2
20	MDN2
21	DGND
22	MDP0
23	MDN0
24	DGND
25	MCP
26	MCN
27	DGND
28	MDP1
29	MDN1
30	DGND



# Main FLASHLIGHT



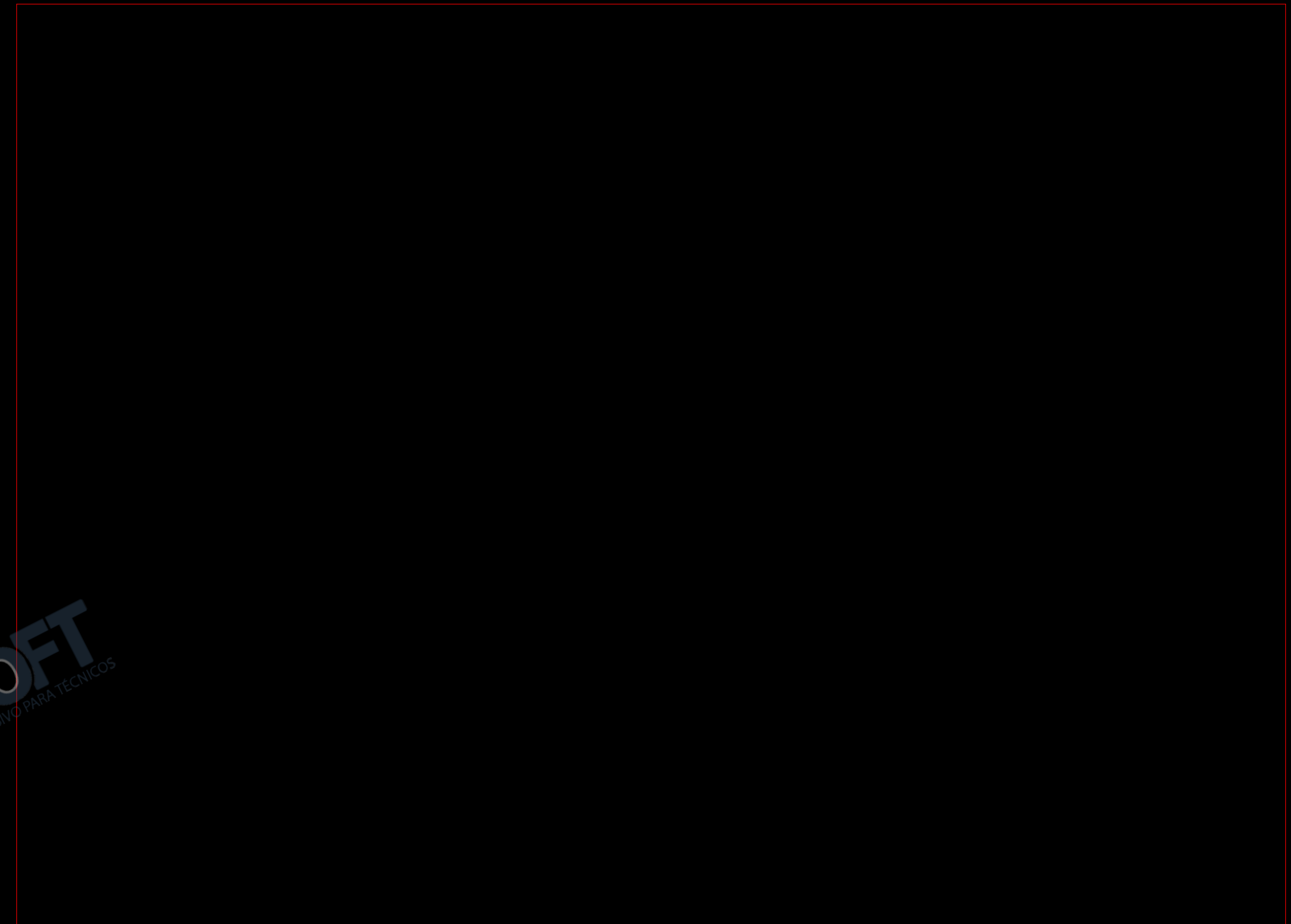
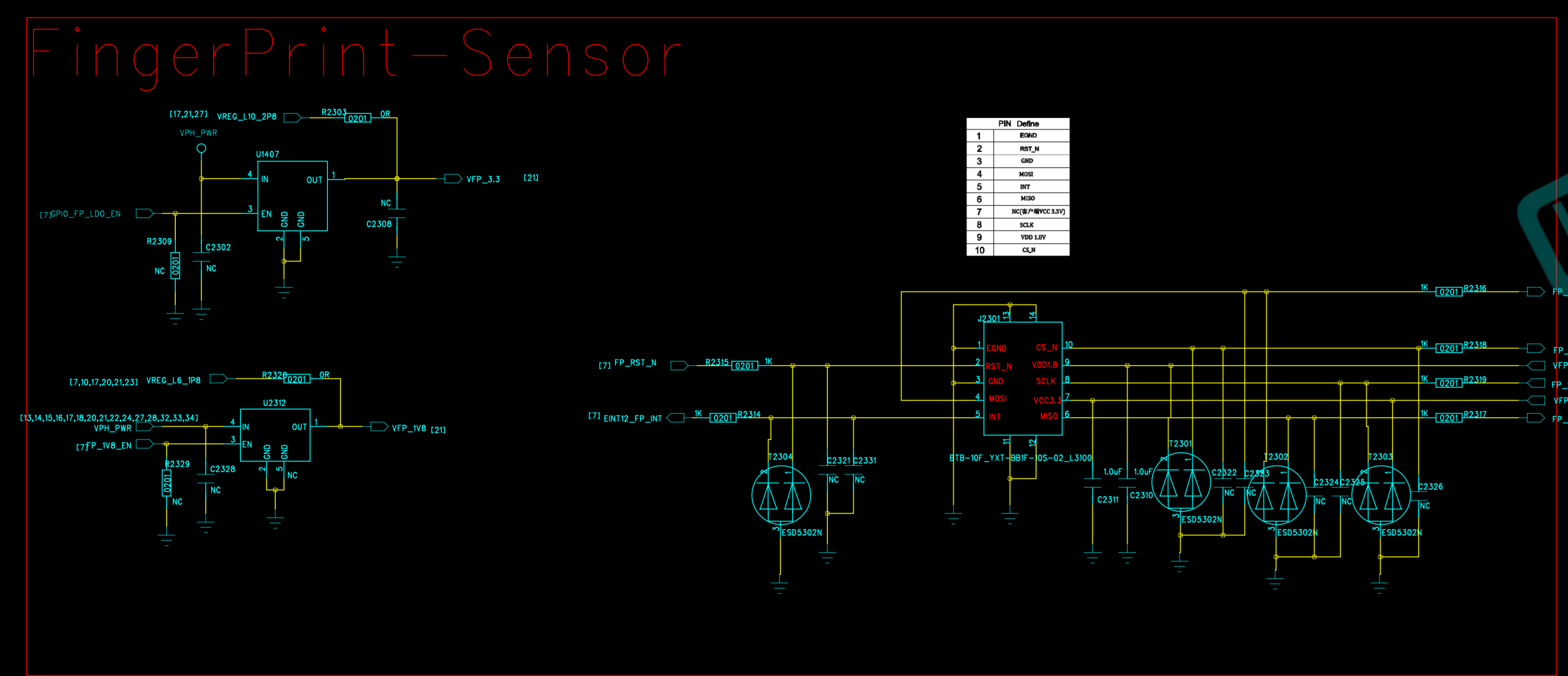
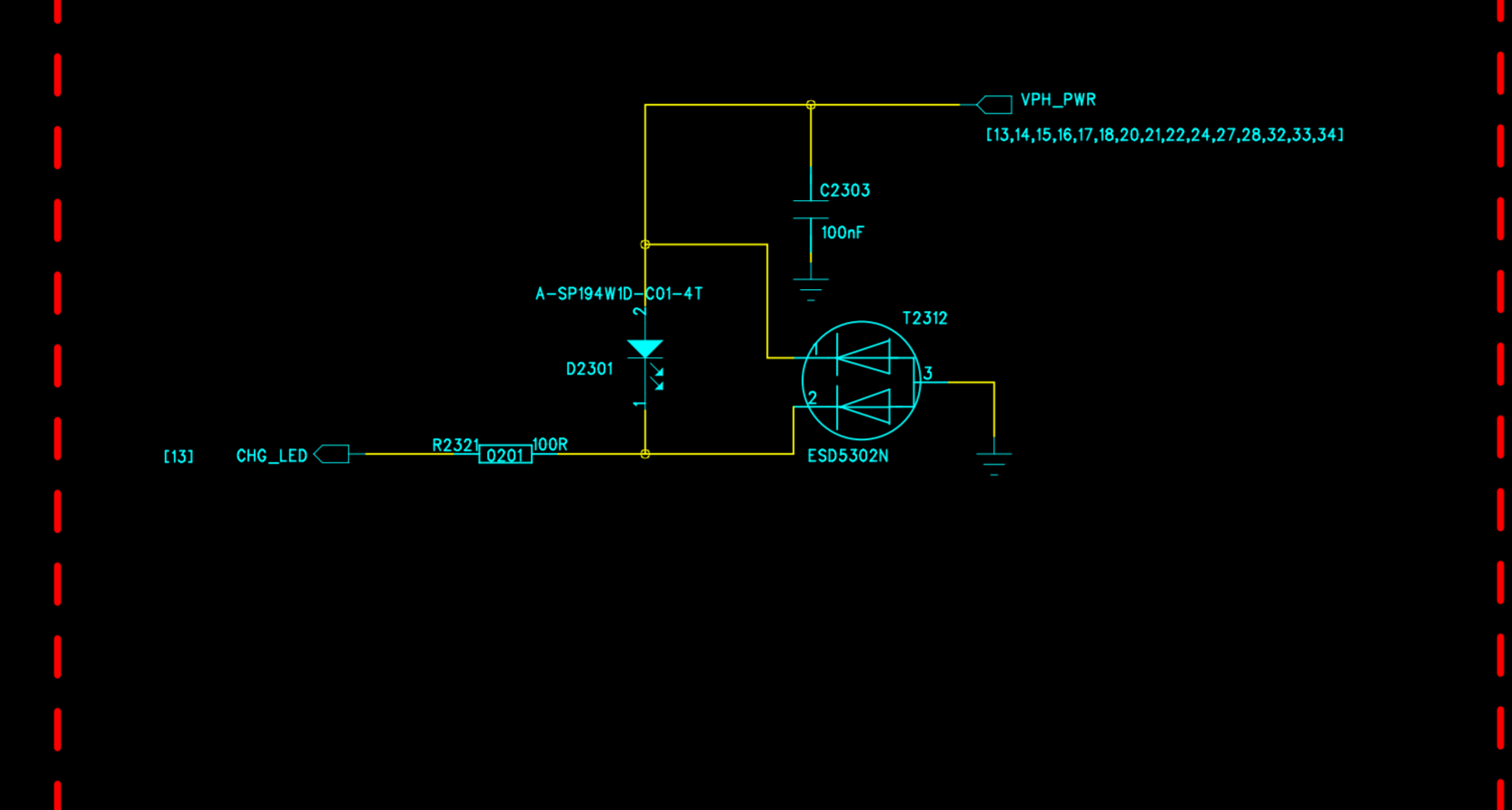
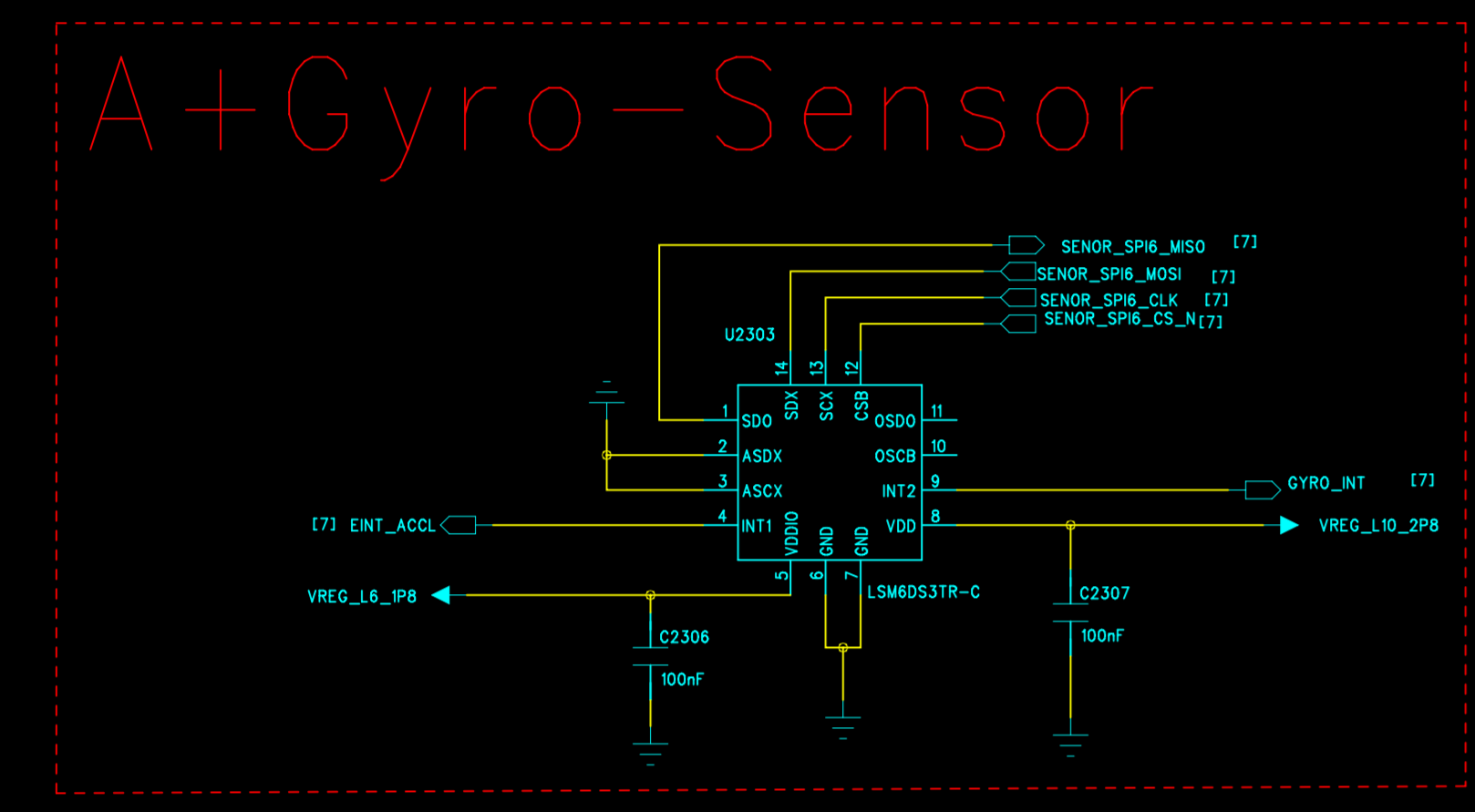
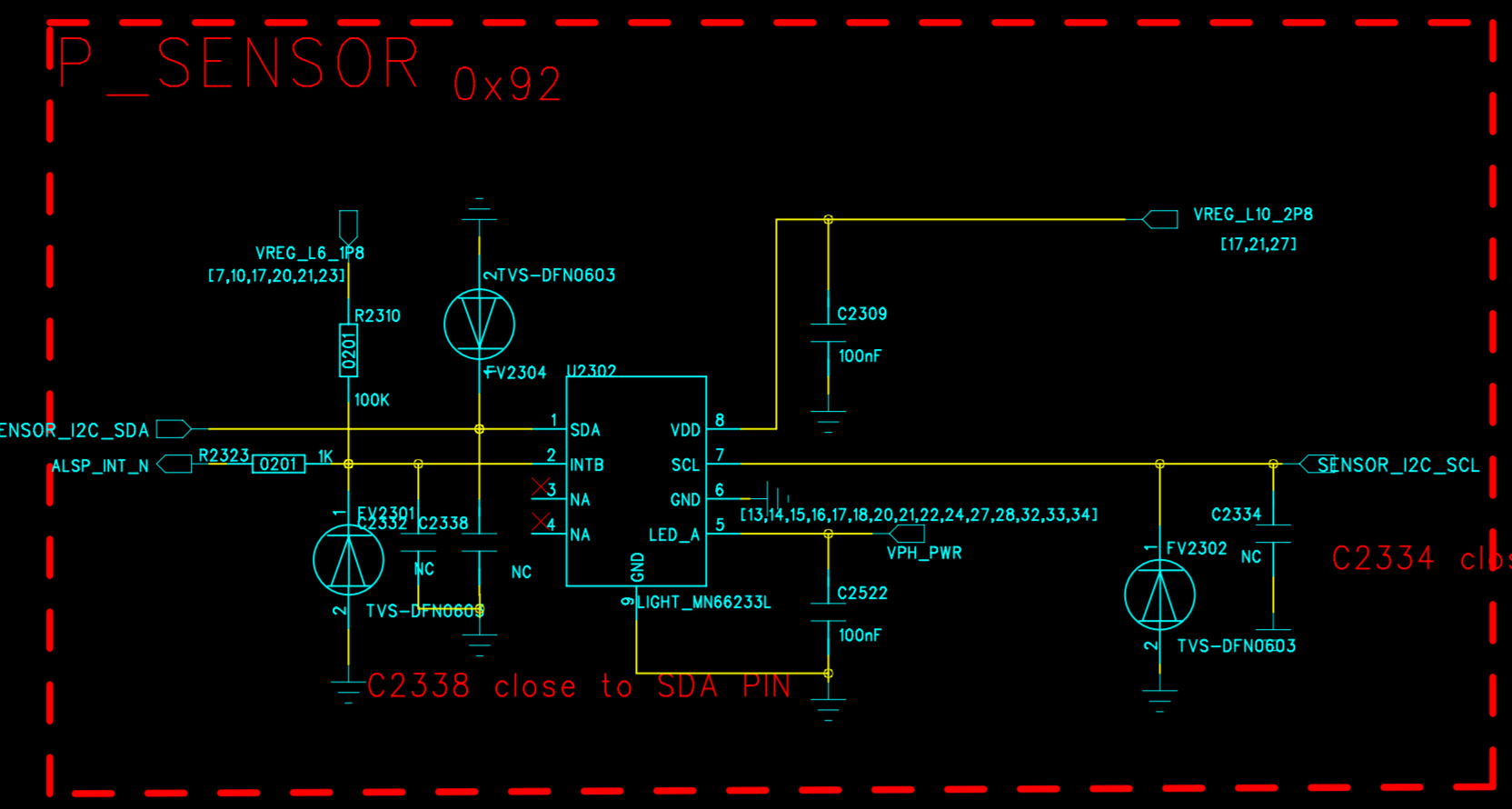
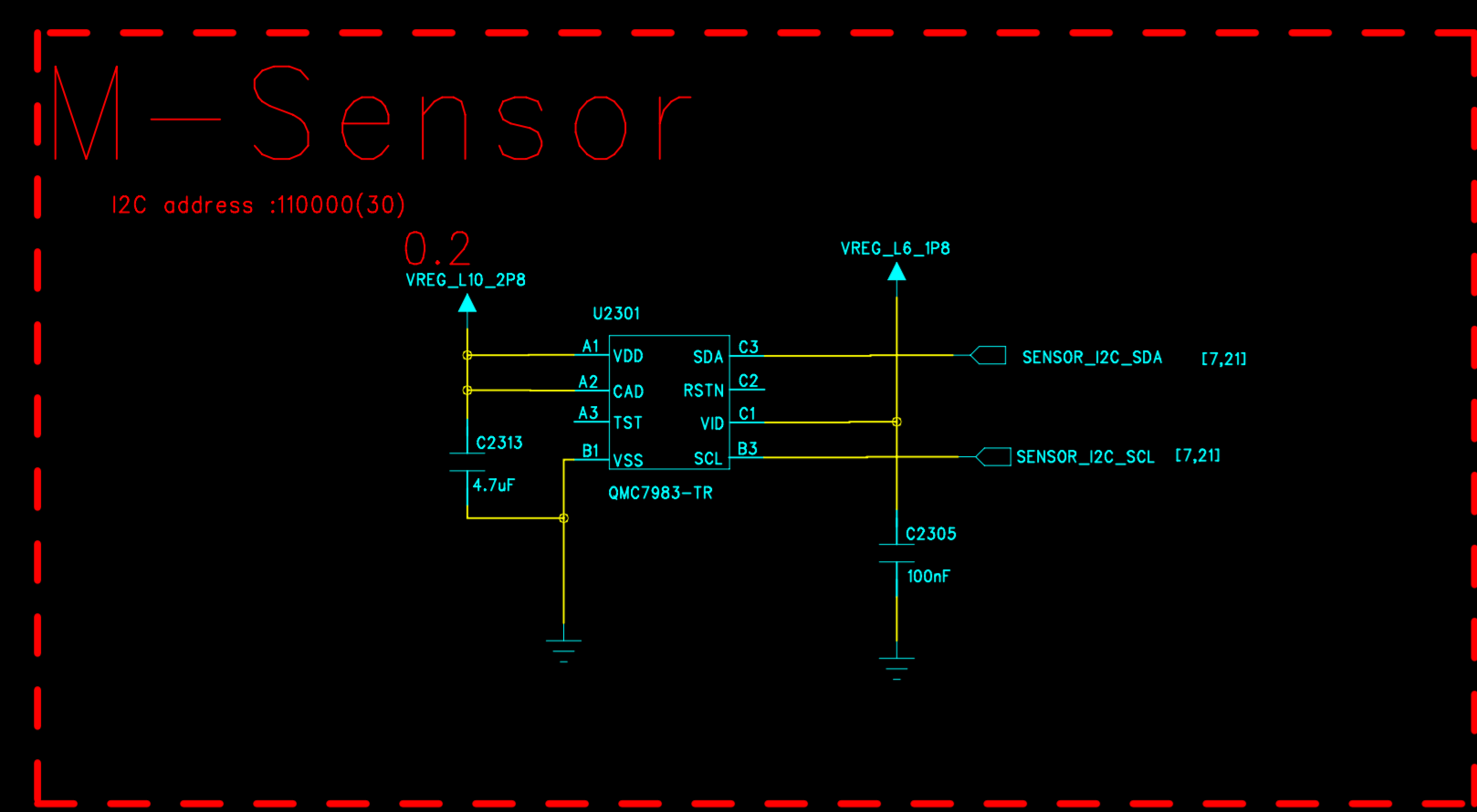
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TITLE: <Title>

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MARK POINT

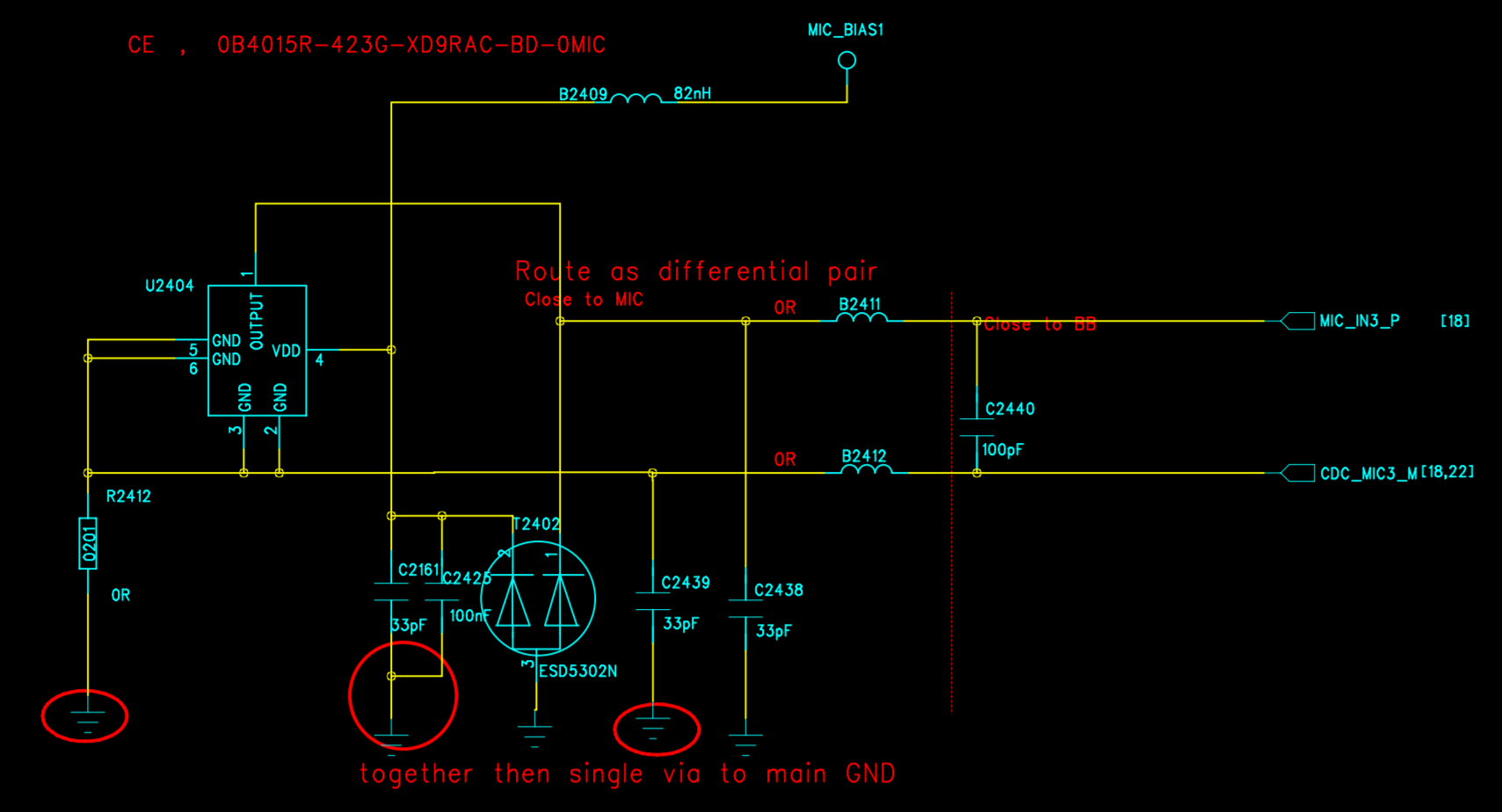


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RELEASED: <Released By>	DATE: <Release Date>	SHEET: 21 OF 34			

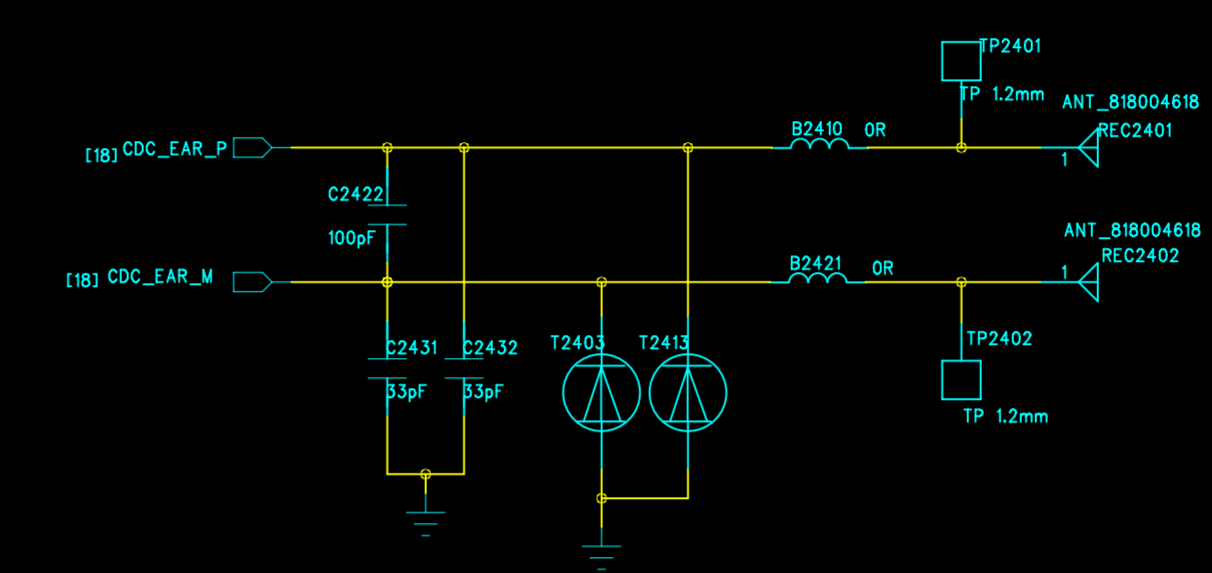


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REV	ECO. NO.	APPROVED	DATE

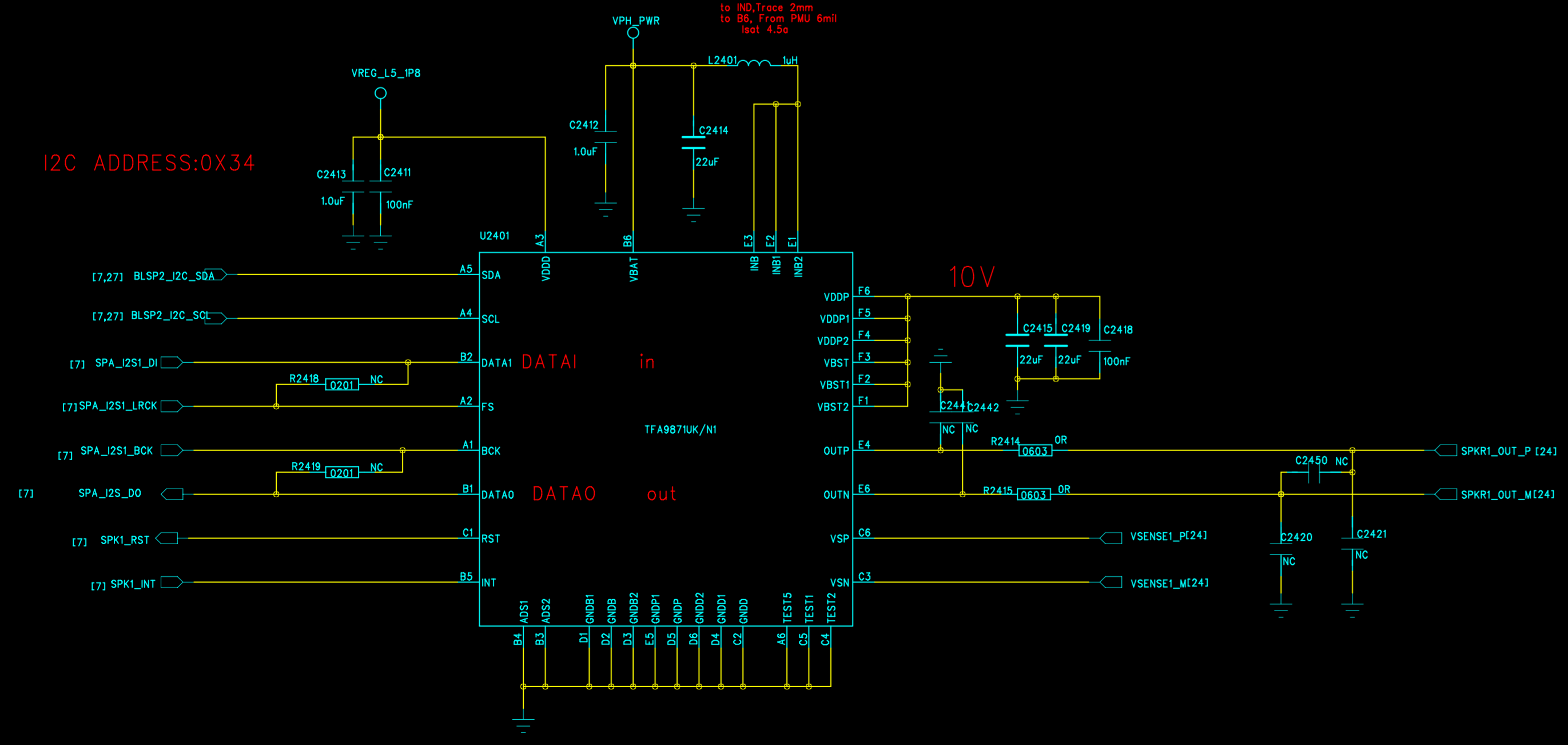
# Sub MIC



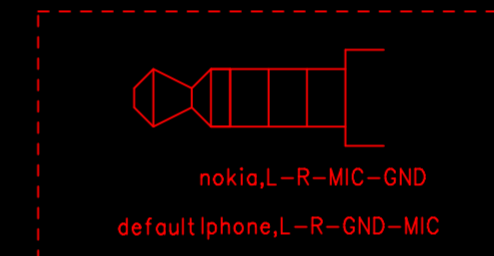
# REC



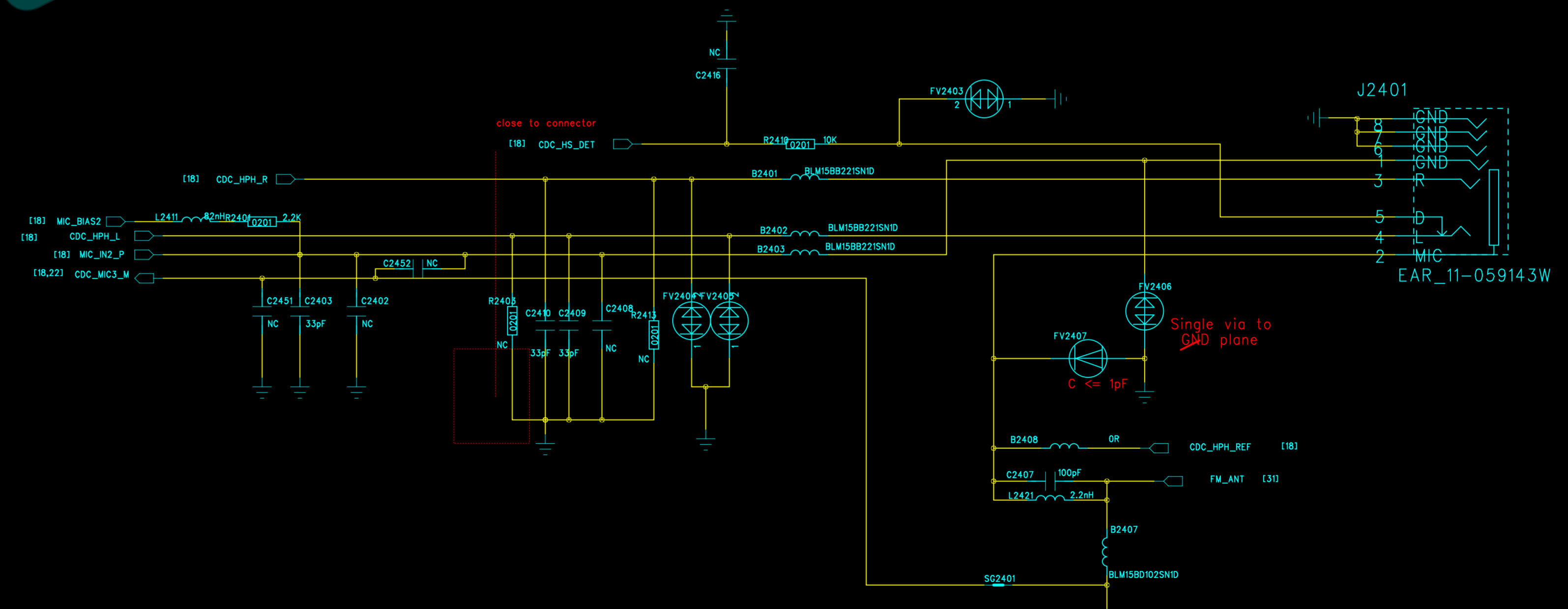
# Audio PA



# Earphone Audio



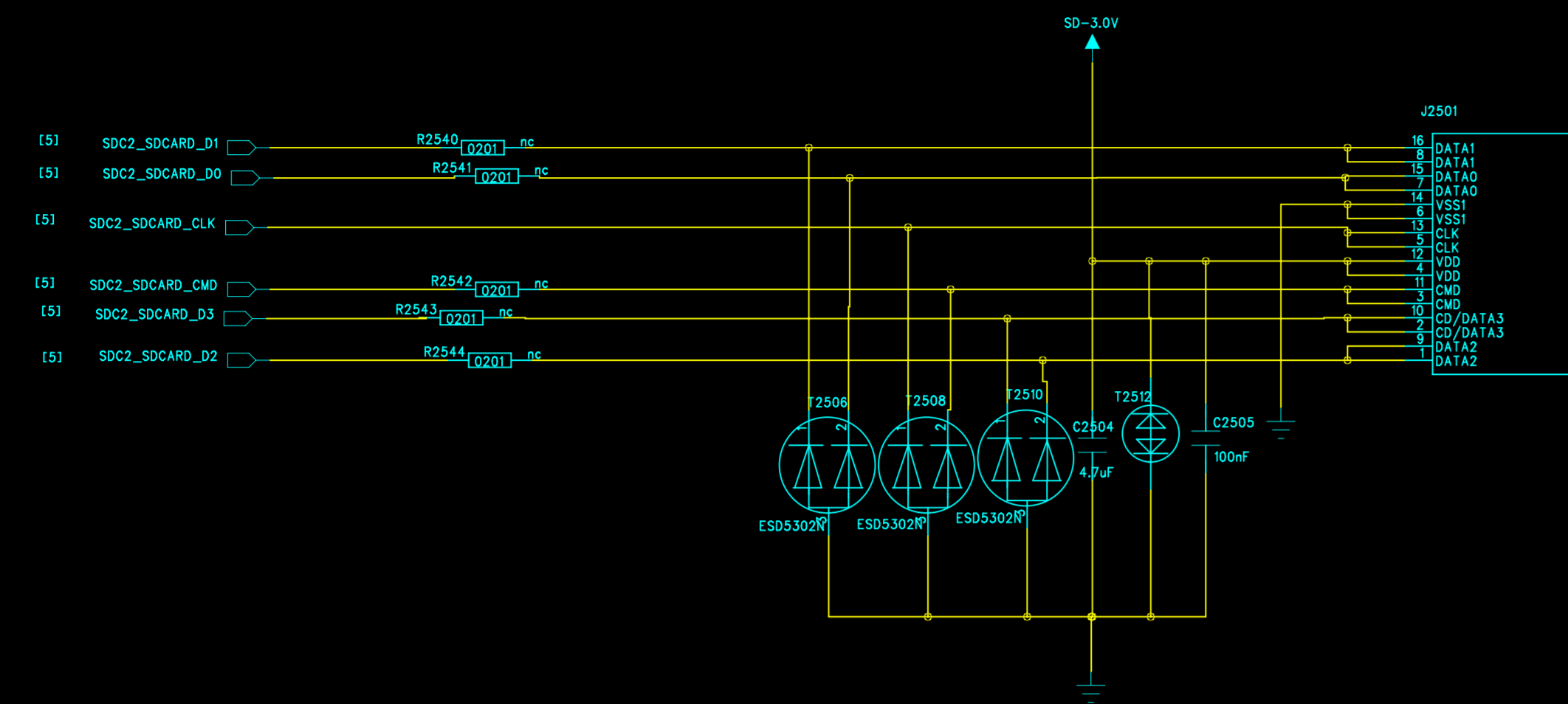
Note: Ferrite beads and their corresponding bypass capacitors on CDC\_HPH\_L\_P, CDC\_HPH\_L\_M and CDC\_HPH\_REF are needed to reduce noise generated by audio/FM concurrency



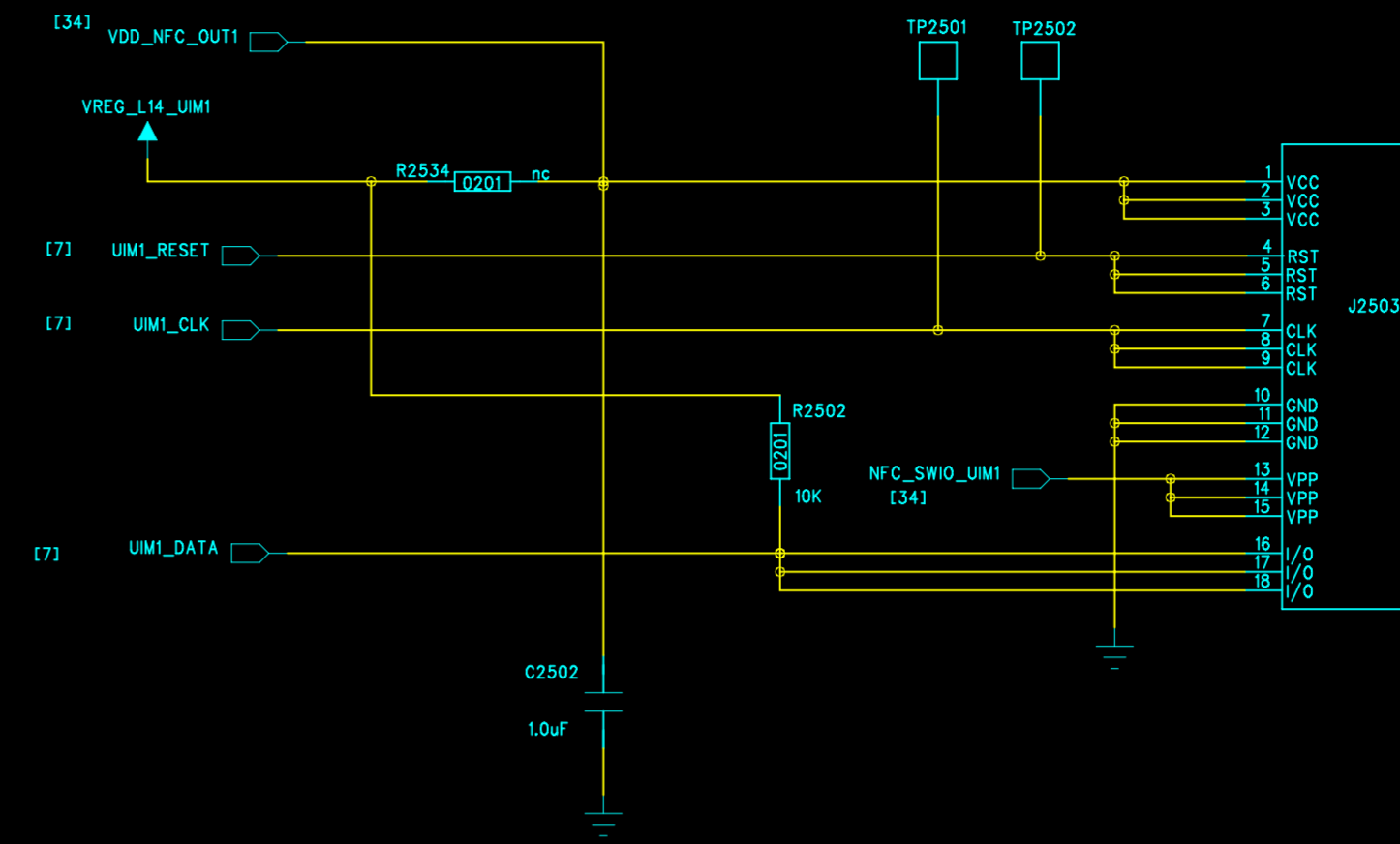
Note: Place B202, B203, C216, C217 close to headset jack connector  
Note: For Cable detection

COMPANY: <Company Name>	
TITLE: <Title>	
DATE: <Drawn By>	DATE: <Drawn Date>
CHECKED: <Checked By>	DATE: <Checked Date>
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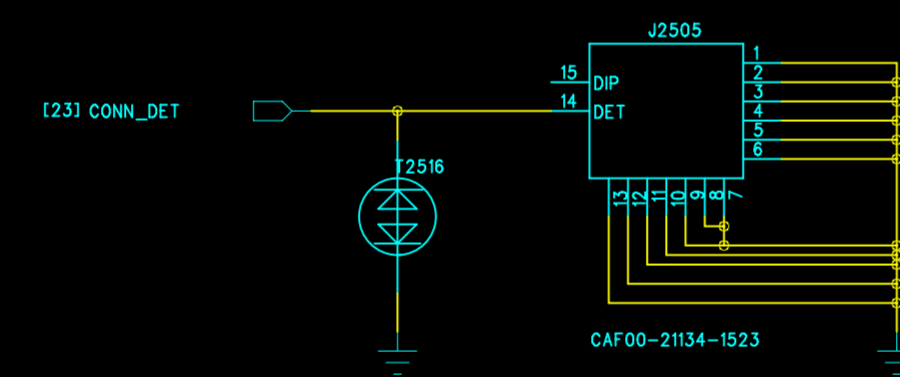
# T-Card



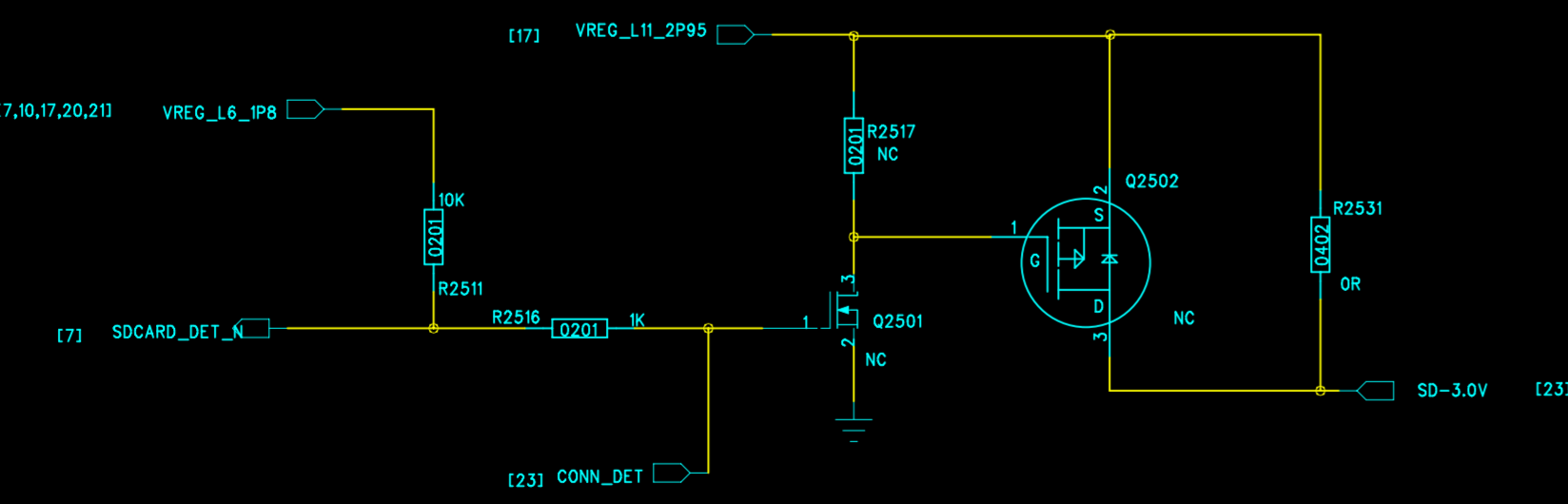
# SIM1



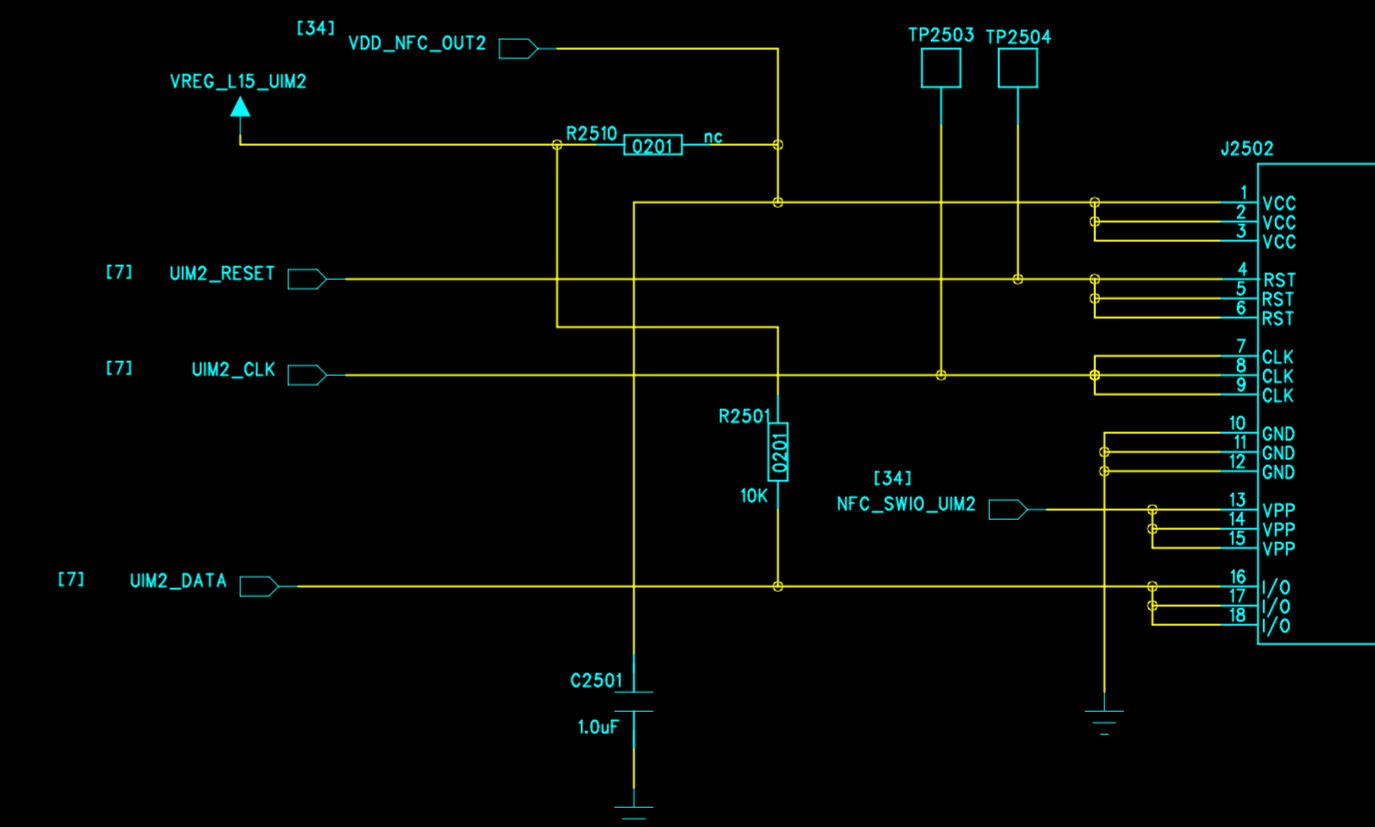
# INT



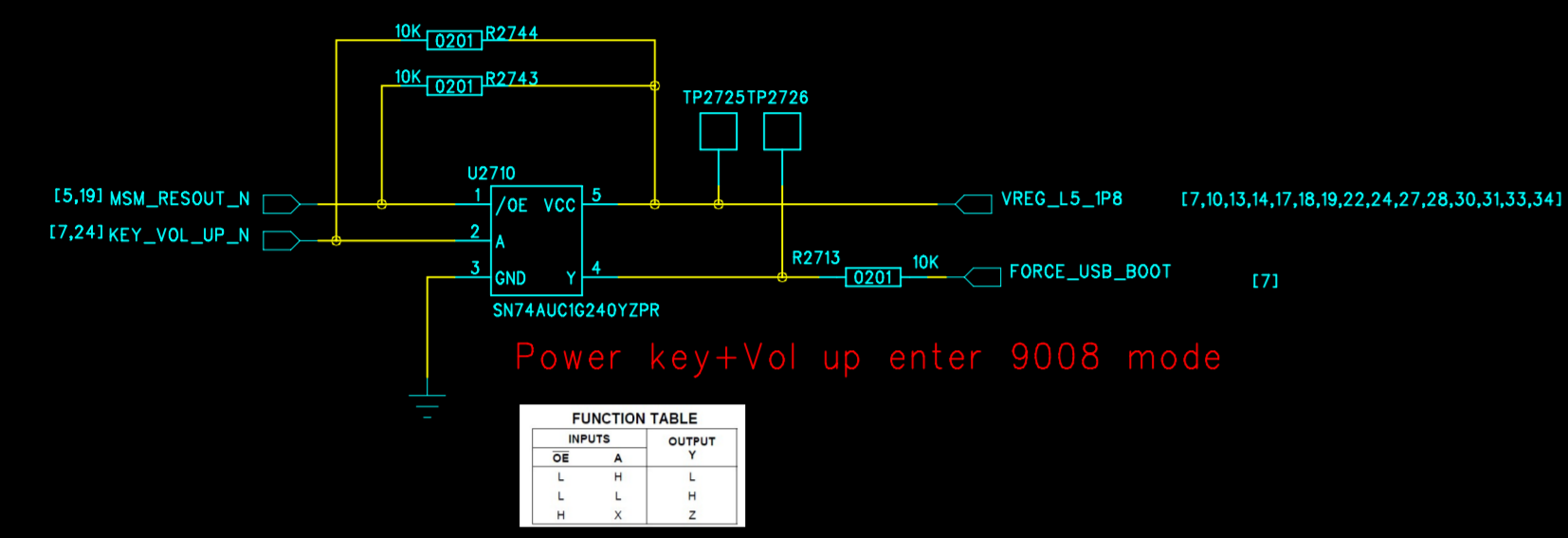
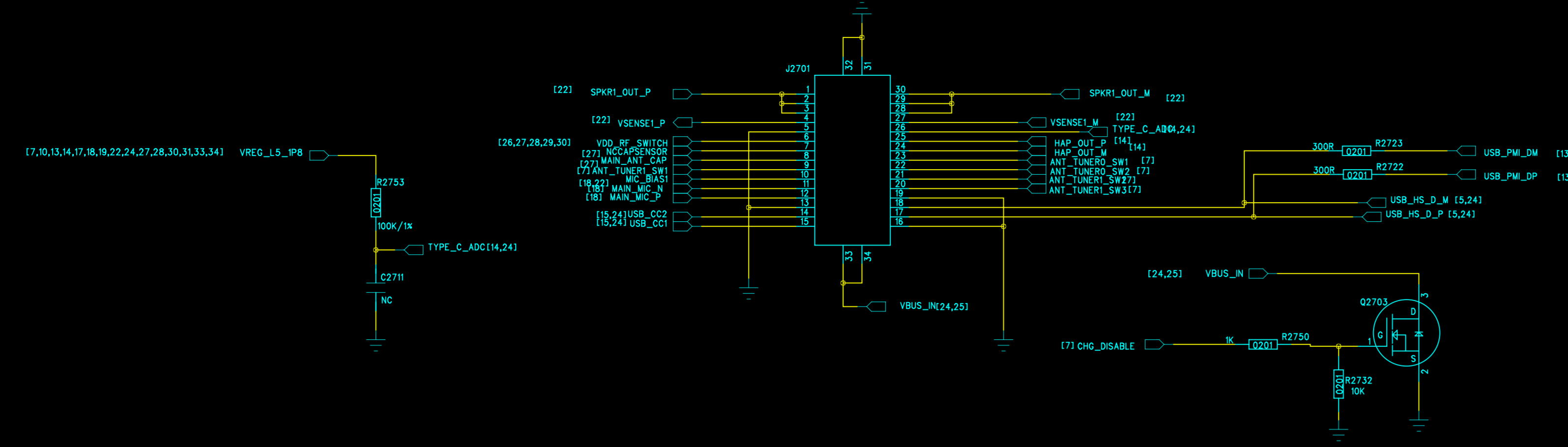
# TF SWITCH



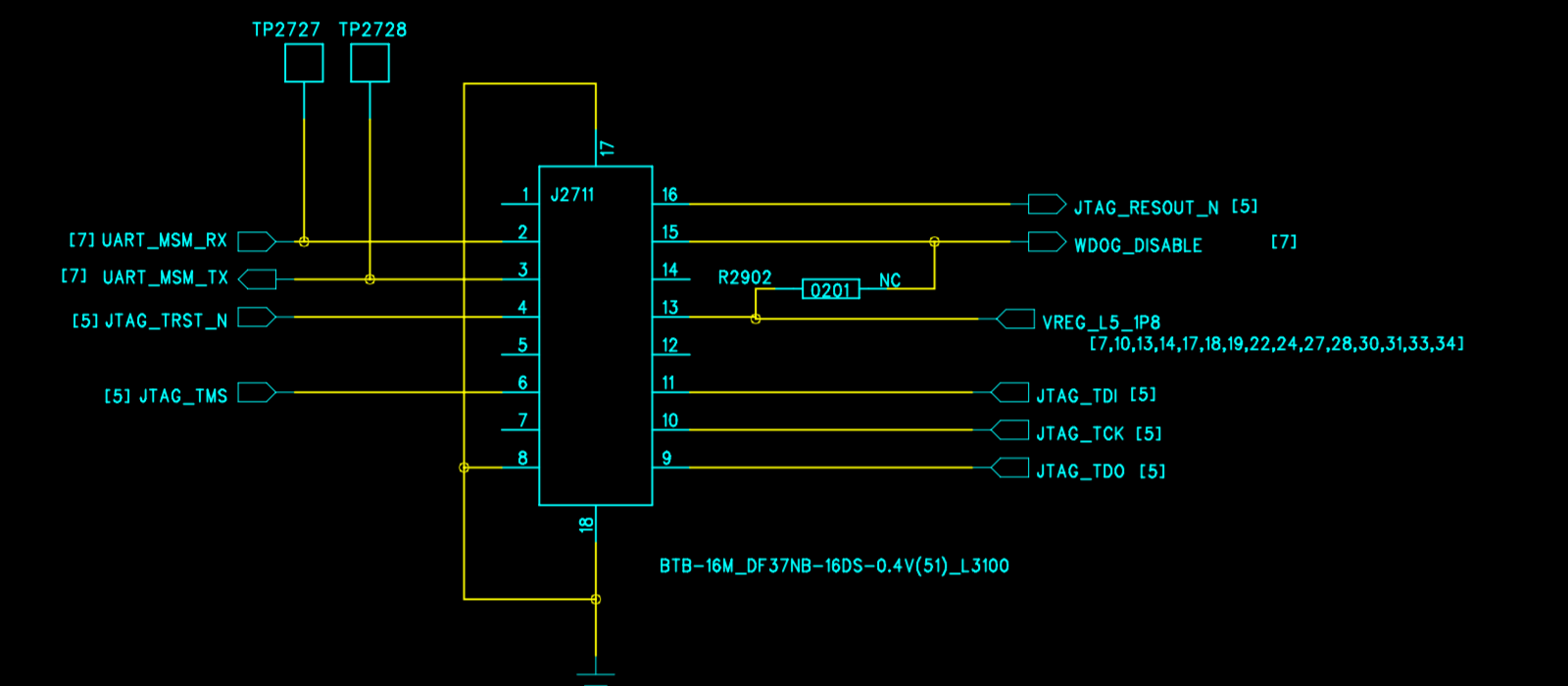
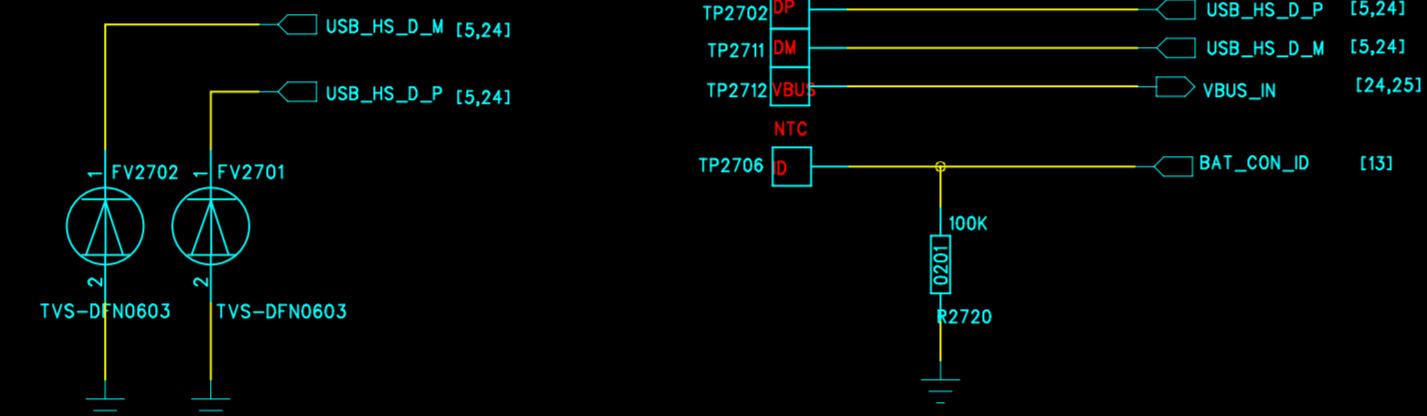
# SIM2



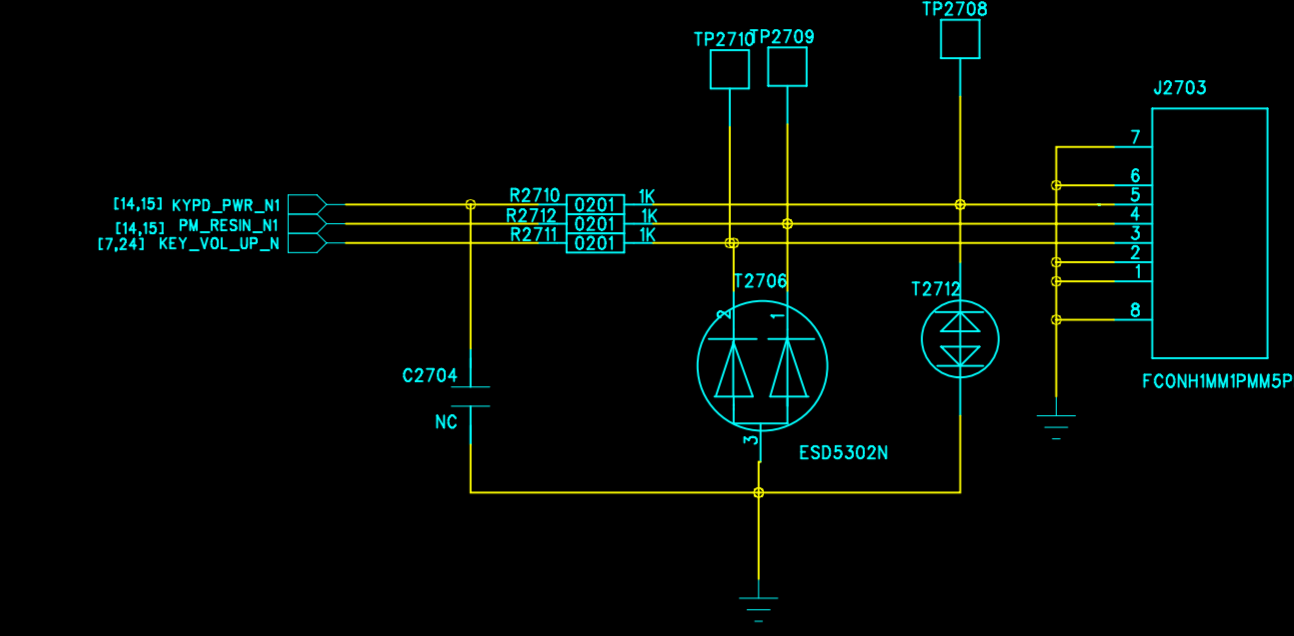
# SUB\_FPC



# Test point



# Power Key

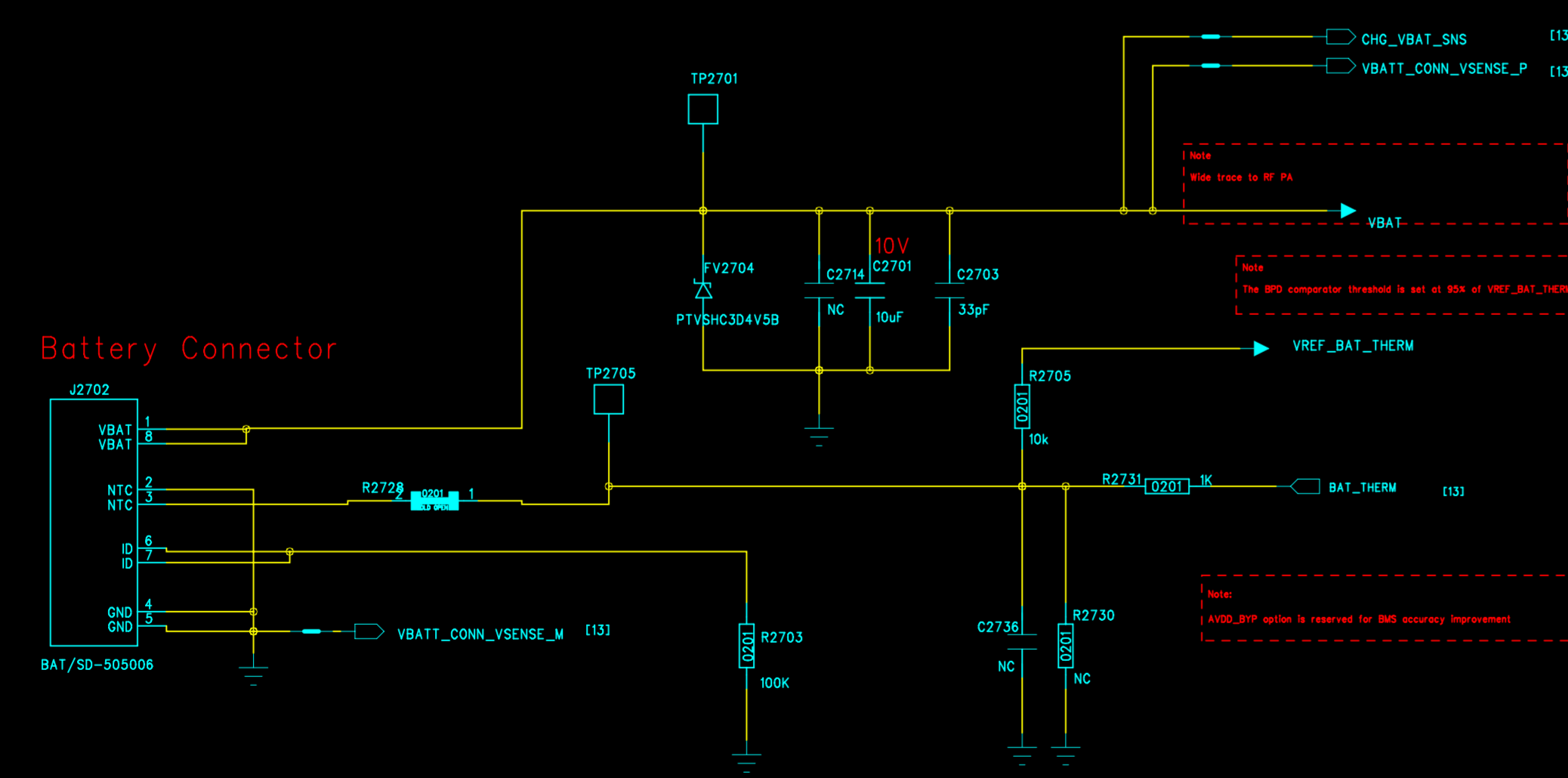


Schematic design notice of "65\_PERI\_Dual\_SIM\_ICUSB\_KEYPAD" page.

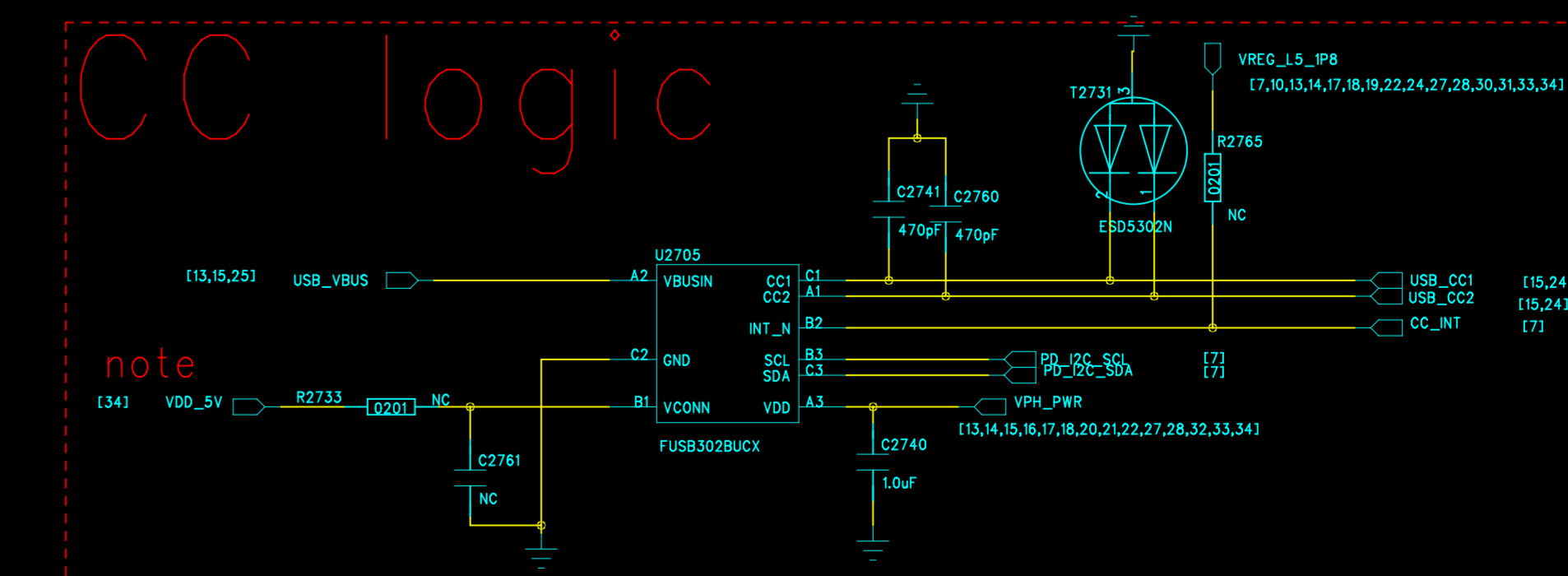
Note 65-1: DO NOT put pull-up resistor on PWRKEY

Note 65-2: Volume Up : HOME Key / GND  
Volume Down : (KPROW0/KPCOL0) or KPCOL0 / GND

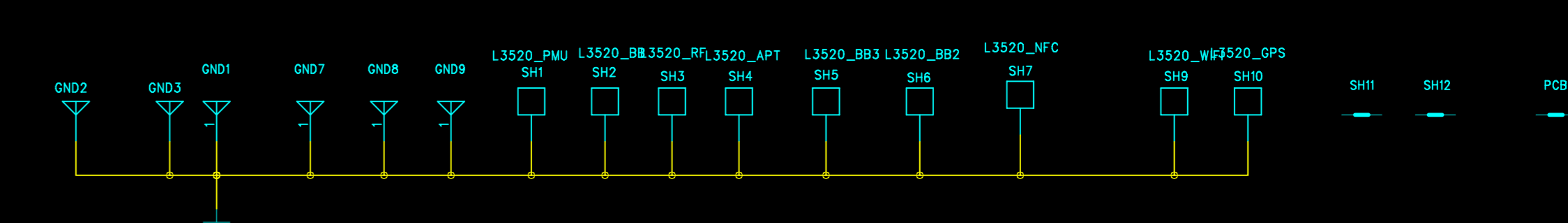
# BAT



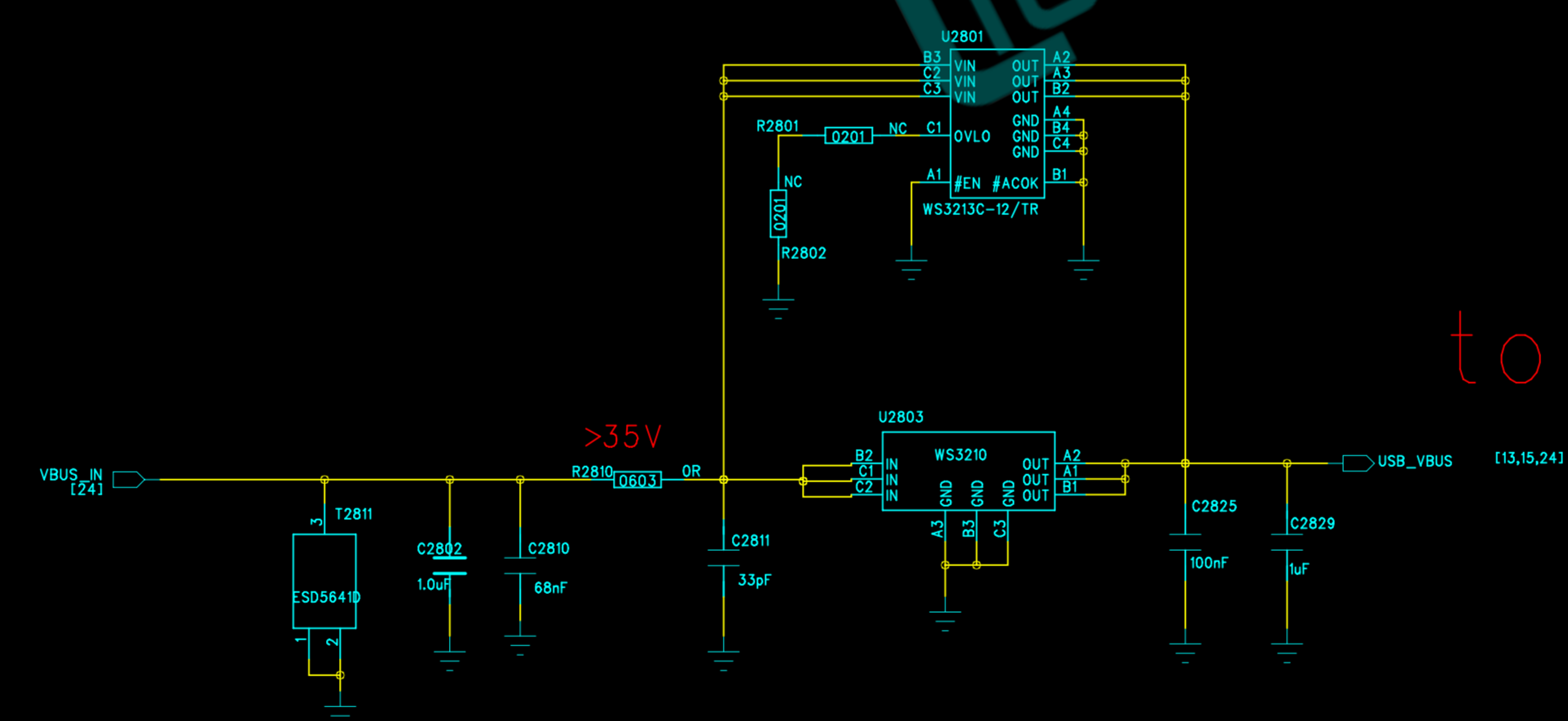
Note:  
Battery ID resistor value require 20K~150K,  
Add 100K to ground if battery package ID not meet requirement



note



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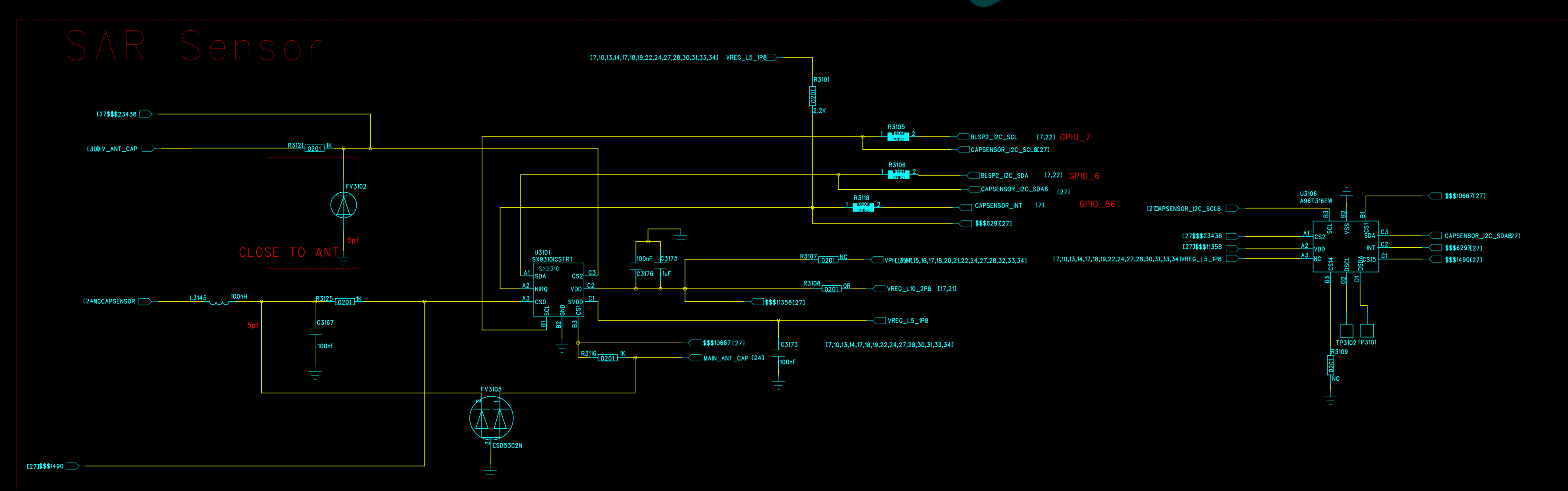
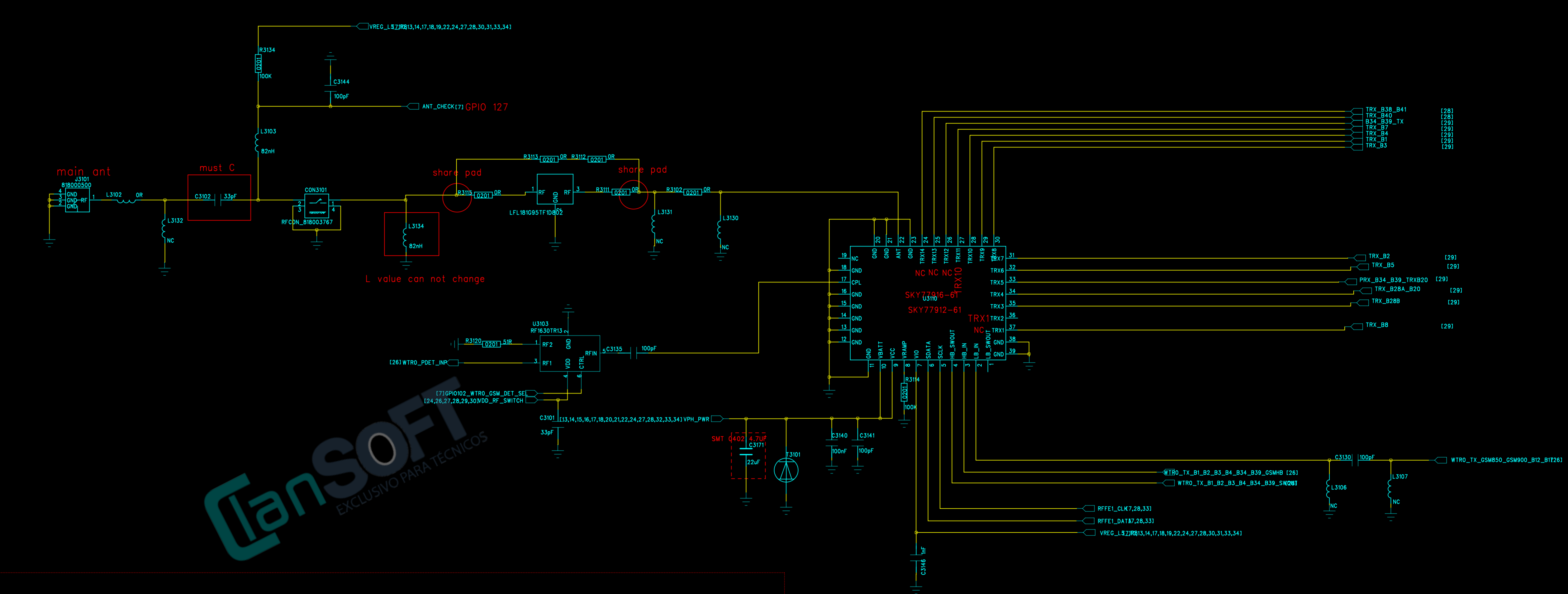
to charger IC

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RELEASED:	DATE:	SCALE: <Scale>		SHEET: 25 of 34	
<Released By>	<Release Date>				





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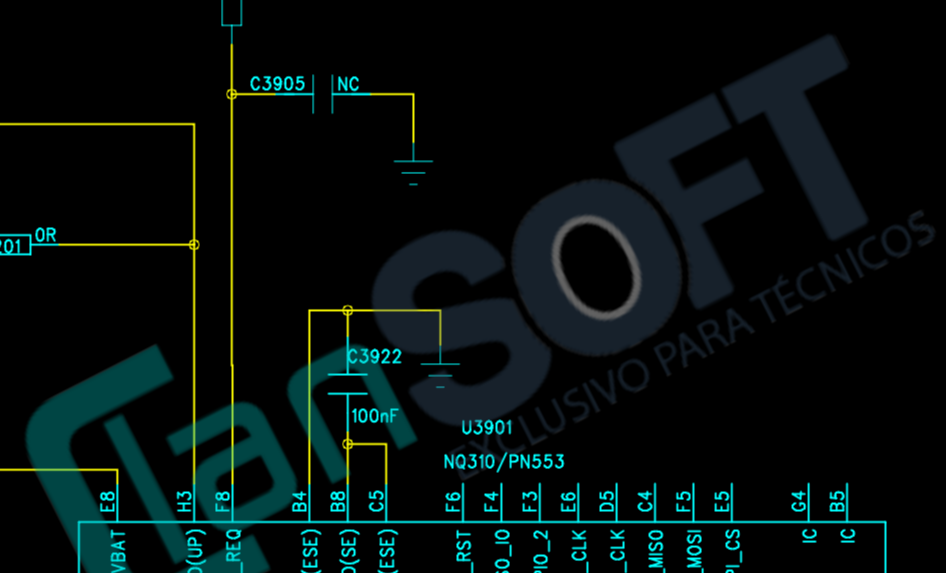
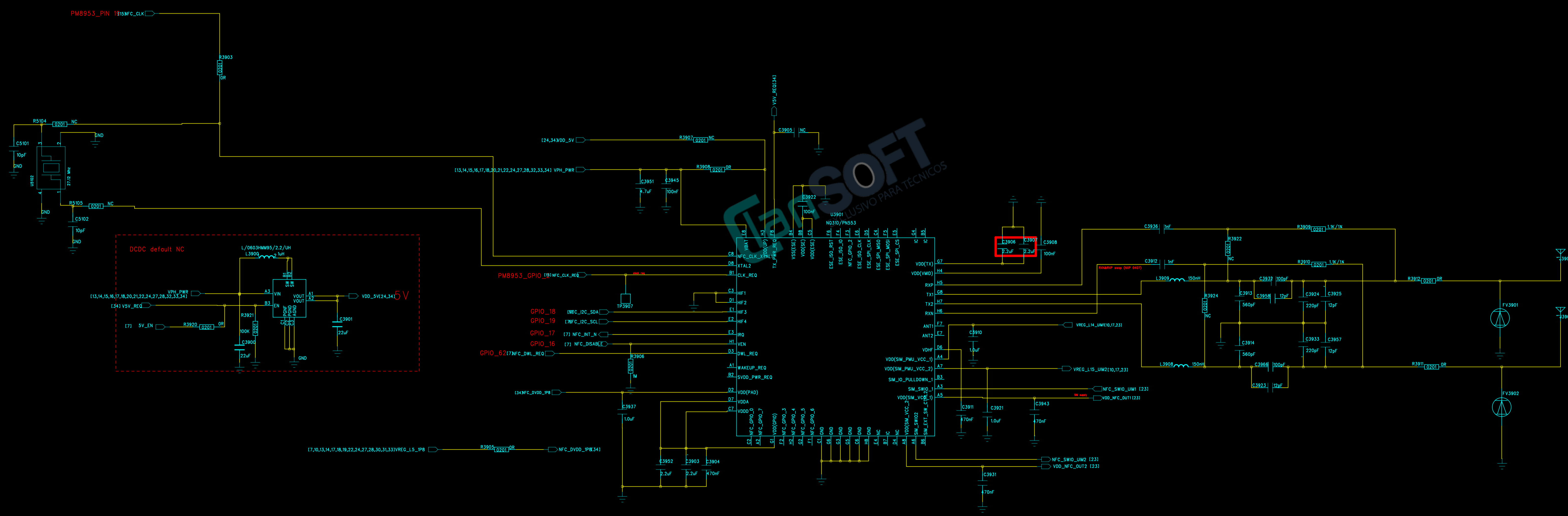








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